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## Ultra Fast USB 2.0 Hub and Multi-Format Flash Media Controller with Dual SD Interfaces

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### General Description

The Microchip USB2660/USB2660i is a USB 2.0 compliant, Hi-Speed hub, card reader, and protocol converter combo solution. This fully integrated single chip solution provides USB expansion and flash card media reader/writer integration. The Microchip USB2660/USB2660i provides an ultra fast interface between a USB host and today's popular flash media formats. The controller allows read/write capability to flash media from the following families:

- Secure Digital™ (SD)
- MultiMediaCard™ (MMC)
- Memory Stick® (MS)
- xD-Picture Card™ (xD)<sup>1</sup>

The USB2660/USB2660i offers a versatile, cost-effective, and energy-efficient hub controller with 2 downstream USB 2.0 ports. This combo solution leverages Microchip's innovative technology that delivers industry-leading data throughput in mixed-speed USB environments. Average sustained transfer rates exceeding 35 MB/s are possible<sup>2</sup>.

### Highlights

- 2 exposed Hi-Speed USB 2.0 downstream ports for external peripheral expansion
- The dedicated flash media reader is internally attached to a 3rd downstream port of the hub as a USB Compound Device
  - a single or multiplexed flash media reader interface
  - a non-multiplexed SD interface (slot) for SD card reader
- **PortMap** - Flexible port mapping and port disable sequencing supports multiple platform designs
- **PortSwap** - Programmable USB differential-pair pin locations eases PCB design by aligning USB signal traces directly to connectors
- **PHYBoost** - Programmable USB transceiver drive strength recovers signal integrity

### Features

- Compliance with the following flash media card specifications SD 2.0 / MMC 4.2 / MS 1.43 / MS-Pro 1.02 / MS-Pro-HG 1.01 / MS-Duo 1.10 / xD 1.2
- Supports a single external 3.3 V supply source; internal regulators provide 1.8 V internal core voltage for additional bill of materials and power savings
- The transaction translator (TT) in the hub supports operation of Full-Speed and Low-Speed peripherals
- 9 K RAM | 64 K on-chip ROM
- Enhanced EMI rejection and ESD protection performance
- Hub and flash media reader/writer configuration from a single source: External I<sup>2</sup>C® ROM or external SPI ROM
  - Configures internal code using an external I<sup>2</sup>C EEPROM
  - Supports external code using an SPI Flash EEPROM
  - Customizable vendor ID, product ID, and language ID if using an external EEPROM
- Additional SD port for card reader
- The USB2660 supports the commercial temperature range of 0°C to +70°C
- The USB2660i supports the industrial temperature range of -40°C to +85°C
- 64-pin QFN RoHS compliant package (9 x 9 mm)

### Applications

- Desktop and mobile PCs
- Printers
- GPS navigation systems
- Media players/viewers
- Consumer A/V
- Set-top boxes
- Industrial products

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1. For xD-Picture Card™ support, please obtain a user license from the xD-Picture Card License Office.

2. Host and media dependent.

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# USB2660/USB2660i

## 1.0 OVERVIEW

The Microchip USB2660/USB2660i is an integrated USB 2.0 compliant, Hi-Speed hub, card reader, and protocol converter combo solution. This combo solution supports today's popular multi-format flash media cards. This multi-format flash media controller and USB hub combo features two exposed downstream USB ports available for external peripheral expansion. The dedicated flash media reader/writer is internally attached to a third downstream port of the hub as a USB Compound Device which supports the following two interfaces: One interface is multiplexed for xD-Picture Card, Memory Stick, Secure Digital/MultiMediaCard, and SD/Secure Digital Input/Output. The other interface is dedicated to a second SD card slot.

The USB2660/USB2660i will attach to an upstream port as a Full-Speed hub or as a Full-/Hi-Speed hub. The hub supports Low-Speed, Full-Speed, and Hi-Speed (if operating as a Hi-Speed hub) downstream devices on all of the enabled downstream ports.

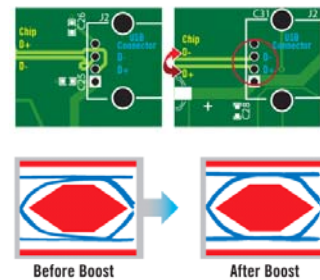
All required resistors on the USB ports are integrated into the hub. This includes all series termination resistors on D+ and D- pins and all required pull-down and pull-up resistors. The over-current sense inputs for the downstream facing ports have internal pull-up resistors.

The USB2660/USB2660i includes programmable features such as:

**PortMap** which provides flexible port mapping and disable sequences. The downstream ports of a USB2660/USB2660i hub can be reordered or disabled in any sequence to support multiple platform designs with minimum effort. For any port that is disabled, the USB2660/USB2660i automatically reorders the remaining ports to match the USB host controller's port numbering scheme.

**PortSwap** which adds per-port programmability to USB differential-pair pin locations. PortSwap allows direct alignment of USB signals (D+/D-) to connectors avoiding uneven trace length or crossing of the USB differential signals on the PCB.

**PHYBoost** which enables four programmable levels of USB signal drive strengths in downstream port transceivers. PHYBoost attempts to restore USB signal integrity. The diagram on the right shows an example of Hi-Speed USB eye diagrams before (PHYBoost at 0%) and after (PHYBoost at 12%) signal integrity restoration in a compromised system environment.



### 1.1 Hardware Features

- Single chip hub and flash media controller combo
- USB2660 supports the commercial temperature range of 0°C to +70°C
- USB2660i supports the industrial temperature range of -40°C to +85°C
- Transaction translator (TT) in the hub supports operation of FS and LS peripherals
- Full power management with individual or ganged power control of each downstream port
- Optional support for external firmware access via SPI interface
- Onboard 24 MHz crystal driver circuit
- Optional external 24 MHz clock input which must be a 1.8 V signal
- Code execution via SPI ROM which must meet
  - 30 MHz or 60 MHz operation support
  - Single bit or dual bit mode support
  - Mode 0 or mode 3 SPI support

#### 1.1.1 COMPLIANCE WITH THE FOLLOWING FLASH MEDIA CARD SPECIFICATIONS:

- Secure Digital 2.0 / MultiMediaCard 4.2
  - SD 2.0, SD-HS, SD-HC
  - TransFlash™ and reduced form factor media
  - 1/4/8 bit MMC 4.2
- Memory Stick 1.43
- Memory Stick Pro Format 1.02

- Memory Stick Pro-HG Duo Format 1.01
  - Memory Stick, MS Duo, MS-HS, MS Pro-HG, MS Pro
- Memory Stick Duo 1.10
- xD-Picture Card 1.2
- 8051 8-bit microprocessor
  - 60 MHz - single cycle execution
  - 64 KB ROM | 9 KB RAM
- Integrated regulator for 1.8 V core operation

## 1.2 Software Features

- Hub and flash media reader/writer configuration from a single source:  
External I<sup>2</sup>C ROM or external SPI ROM
- If the OEM is using an external EEPROM or an external SPI ROM, the following features are available:
  - Customizable vendor ID, product ID, and device ID
  - 12-hex digits maximum for the serial number string
  - 28-character manufacturer ID and product strings for the flash media reader/writer

## 1.3 OEM Selectable Hub Features

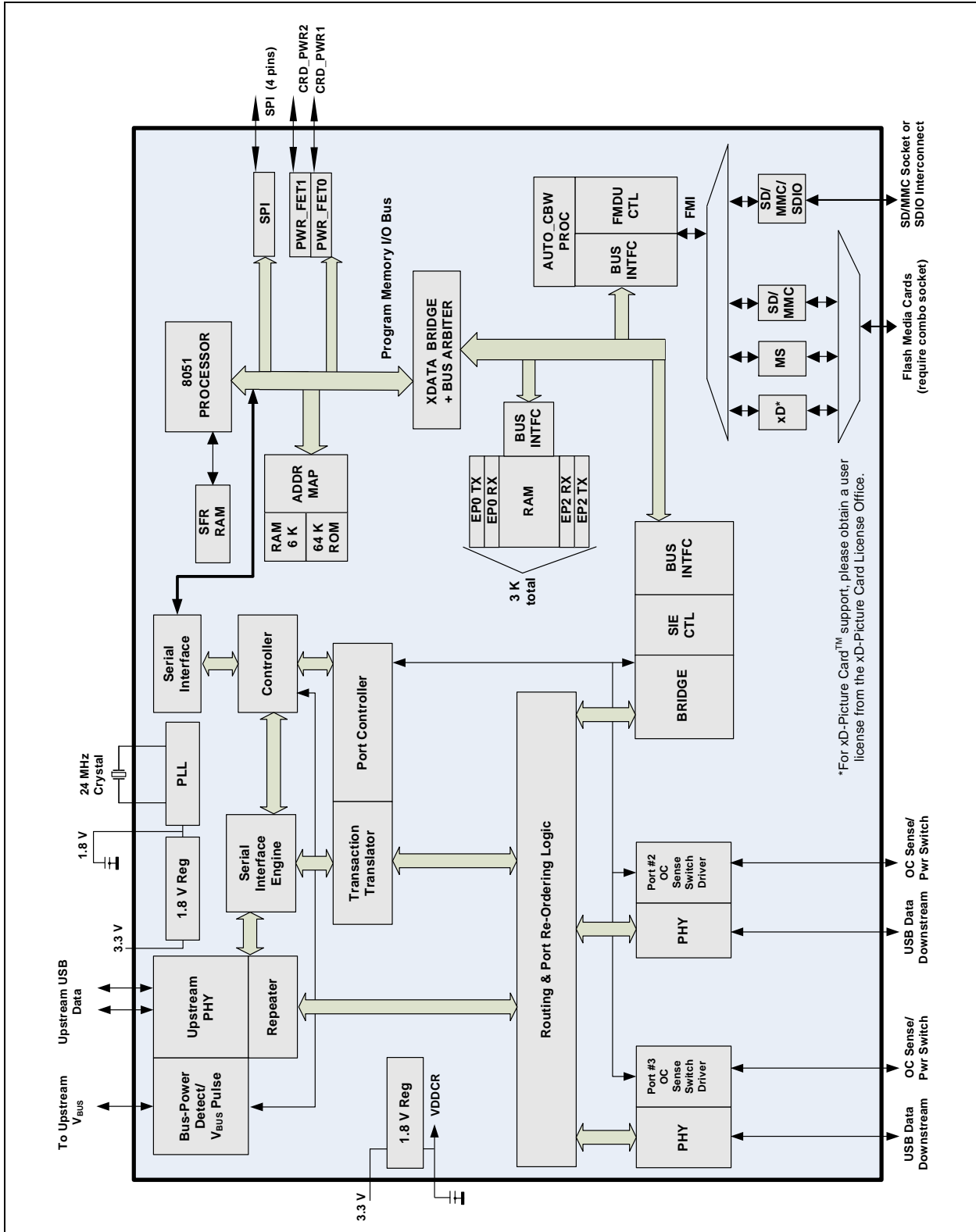
A default configuration is available in the USB2660/USB2660i following a reset. The USB2660/USB2660i may also be configured by an external I<sup>2</sup>C EEPROM or via external SPI ROM flash.

- Compound Device support on a port-by-port basis
  - a port is permanently hardwired to a downstream USB peripheral device
- Select over-current sensing and port power control on an individual or ganged (all ports together) basis to match the OEM's choice of circuit board component selection
- Port power control and over-current detection/delay features
- Configure the delay time for filtering the over-current sense inputs
- Configure the delay time for turning on downstream port power
- Bus- or self-powered selection
- Hub port disable or non-removable configurations
- Flexible port mapping and disable sequencing supports multiple platform designs
- Programmable USB differential-pair pin location eases PCB layout by aligning USB signal lines directly to connectors
- Programmable USB signal drive strength recovers USB signal integrity using 4 levels of signal drive strength
- Indicate the maximum current that the 2-port hub consumes from the USB upstream port
- Indicate the maximum current required for the hub controller

# USB2660/USB2660i

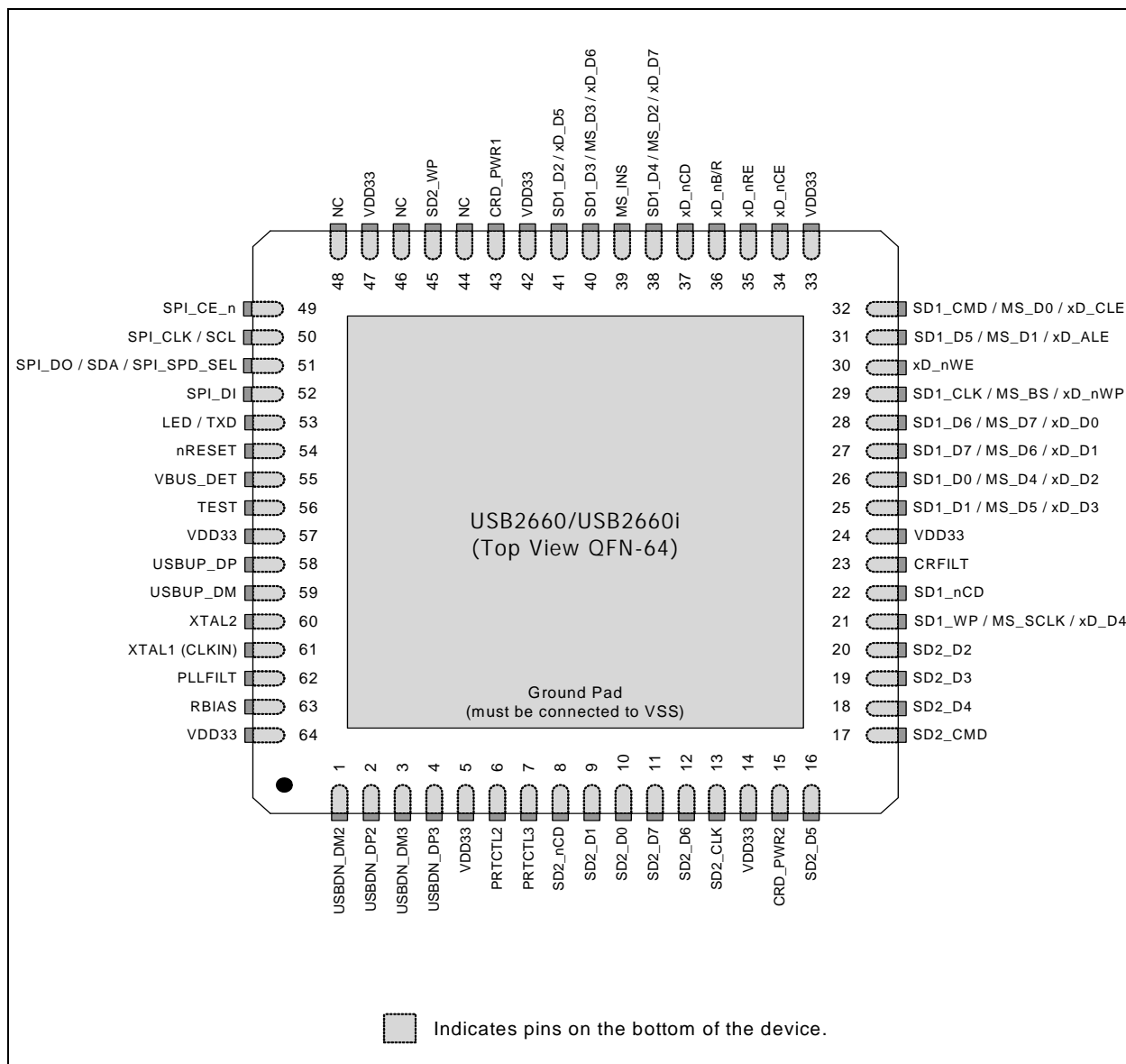
## 2.0 BLOCK DIAGRAM

FIGURE 2-1: USB2660/USB2660I BLOCK DIAGRAM



## 3.0 PIN CONFIGURATION

FIGURE 3-1: USB2660/USB2660i 64-PIN QFN



# USB2660/USB2660i

## 3.1 64-Pin Table

TABLE 3-1: USB2660/USB2660I 64-PIN TABLE

SECURE DIGITAL / MEMORY STICK / xD INTERFACE (18 PINS)			
SD1_D7 / MS_D6 / xD_D1	SD1_D6 / MS_D7 / xD_D0	SD1_D5 / MS_D1 / xD_ALE	SD1_D4 / MS_D2 / xD_D7
SD1_D3 / MS_D3 / xD_D6	SD1_D2 / xD_D5	SD1_D1 / MS_D5 / xD_D3	SD1_D0 / MS_D4 / xD_D2
SD1_CLK / MS_BS / xD_nWP	SD1_CMD / MS_D0 / xD_CLE	SD1_nCD	MS_INS
SD1_WP / MS_SCLK / xD_D4	xD_nCD	xD_nB/R	xD_nRE
xD_nCE	xD_nWE		
SECOND SECURE DIGITAL INTERFACE (12 PINS)			
SD2_D7	SD2_D6	SD2_D5	SD2_D4
SD2_D3	SD2_D2	SD2_D1	SD2_D0
SD2_NCD	SD2_CLK	SD2_CMD	SD2_W
USB INTERFACE (5 PINS)			
USBUP_DP	USBUP_DM	XTAL1 (CLKIN)	XTAL2
RBIAS			
2-PORT USB INTERFACE (7 PINS)			
USBDN_DP2	USBDN_DM2	PRTCTL2	PRTCTL3
USBDN_DP3	USBDN_DM3	VBUS_DET	
SPI INTERFACE (4 PINS)			
SPI_CE_n	SPI_CLK / SCL	SPI_DO / SDA / SPI_SPD_SEL	SPI_DI
MISC (8 PINS)			
nRESET	TEST	LED	
CRD_PWR2	CRD_PWR1	(3) NC	
POWER (10 PINS)			
(8) VDD33	CRFILT	PLLFILT	
TOTAL 64			



## 4.0 PIN DESCRIPTIONS

This section provides a detailed description of each signal. The signals are arranged in functional groups according to their associated interface. The pin descriptions below are applied when using the internal default firmware and can be referenced in [Section 6.0, "Configuration Options," on page 22](#). Please reference [Section Appendix A: "Acronyms," on page 55](#) for a list of the acronyms used.

The "n" symbol in the signal name indicates that the active, or asserted, state occurs when the signal is at a low voltage level. When "n" is not present in the signal name, the signal is asserted at a high voltage level.

The terms assertion and negation are used exclusively. This is done to avoid confusion when working with a mixture of "active low" and "active high" signals. The term assert, or assertion, indicates that a signal is active, independent of whether that level is represented by a high or low voltage. The term negate, or negation, indicates that a signal is inactive.

### 4.1 USB2660/USB2660i Pin Descriptions

**TABLE 4-1: USB2660/USB2660I PIN DESCRIPTIONS**

Symbol	64-PIN QFN	Buffer Type (Table 4-2)	Description
<b>SECURE DIGITAL INTERFACE</b>			
SD1_D[7:0]	27 28 31 38 40 41 25 26	I/O8PU	Secure Digital Data 7-0  These are the bi-directional data signals SD_D0 - SD_D7 with weak pull-up resistors.
SD1_CLK	29	O8	Secure Digital Clock  This is an output clock signal to the SD/MMC device.
SD1_CMD	32	I/O8PU	Secure Digital Command  This is a bi-directional signal that connects to the CMD signal of the SD/MMC device. The bi-directional signal has a weak internal pull-up resistor.
SD1_nCD	22	I/O8PU	Secure Digital Card Detect  Designates as the Secure Digital card detection pin and has an internal pull-up.
SD1_WP	21	I/O8	Secure Digital Write Protected  Designates as the Secure Digital card mechanical write protect detect pin.
<b>SECOND SECURE DIGITAL INTERFACE</b>			
SD2_D[7:0]	11 12 16 18 19 20 9 10	I/O8PU	SD2 Data 7-0  These are the bi-directional data signals SD2_D0 - SD2_D7 and have weak pull-up resistors.
SD2_CLK	13	O8	SD2 Clock  This is an output clock signal designated for to the SD2/MMC device.

# USB2660/USB2660i

**TABLE 4-1: USB2660/USB2660I PIN DESCRIPTIONS (CONTINUED)**

Symbol	64-PIN QFN	Buffer Type (Table 4-2)	Description
SD2_CMD	17	I/O8PU	SD2 Command This is a bi-directional signal designated by for the CMD signal of the SD2/MMC device. The bi-directional signal has a weak internal pull-up resistor.
SD2_nCD	8	I/O8	SD2 Card Detect Designates as the second Secure Digital card detection pin and has an internal pull-up.
SD2_WP	45	I/O8	SD2 Write Protected Designates as the second Secure Digital card interface mechanical write detect pin.
<b>MEMORY STICK INTERFACE</b>			
MS_BS	29	O8	Memory Stick Bus State This pin is connected to the bus state pin of the MS device. It is used to control the Bus States 0, 1, 2, and 3 (BS0, BS1, and BS3) of the MS device.
MS_INS	39	IPU	Memory Stick Card Insertion Designates as the Memory Stick card detection pin and has a weak internal pull-up resistor.
MS_SCLK	21	O8	Memory Stick System Clock This pin is an output clock signal to the MS device.
MS_D[7:0]	28 27 25 26 40 38 31 32	I/O8PD	Memory Stick System Data In/Out These pins are the bi-directional data signals for the MS device. In serial mode, the most significant bit (MSB) of each byte is transmitted first by either MSC or MS device on MS_D0.  MS_D0, MS_D2, and MS_D3 have weak pull-down resistors. MS_D1 has a pull-down resistor if in parallel mode, otherwise it is disabled. In 4- or 8-bit parallel modes, all MS_D7 - MS_D0 signals have weak pull-down resistors.
<b>xD-PICTURE CARD INTERFACE</b>			
xD_D[7:0]	38 40 41 21 25 26 27 28	I/O8PD	xD-Picture Card Data 7-0 These pins are the bi-directional data signals xD_D7 - xD_D0 and have weak internal pull-down resistors.
xD_ALE	31	O8PD	xD-Picture Card Address Strobe This pin is an active high Address Latch Enable (ALE) signal for the xD device. This pin has a weak pull-down resistor that is permanently enabled.

**TABLE 4-1: USB2660/USB2660I PIN DESCRIPTIONS (CONTINUED)**

Symbol	64-PIN QFN	Buffer Type (Table 4-2)	Description
xD_nB/R	36	IPU	<p>xD-Picture Card Busy or Data Ready</p> <p>This pin is connected to the BSY/RDY pin of the xD-Picture Card device.</p> <p>When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET.</p> <p>If an external FET is used (the internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).</p>
xD_nCE	34	O8PU	<p>xD-Picture Card Chip Enable</p> <p>This pin is an active low chip enable signal for the xD-Picture Card device.</p> <p>When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET.</p> <p>If an external FET is used (internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).</p>
xD_CLE	32	O8PD	<p>xD-Picture Card Command Strobe</p> <p>This pin is an active high Command Latch Enable signal for the xD device. This pin has a weak pull-down resistor that is permanently enabled.</p>
xD_nCD	37	I/O8	<p>xD-Picture Card Detection</p> <p>Designates as the xD-Picture Card detection pin.</p>
xD_nRE	35	O8PU	<p>xD-Picture Card Read Enable</p> <p>This pin is an active low read strobe signal for the xD-Picture Card device.</p> <p>When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET.</p> <p>If an external FET is used (internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).</p>
xD_nWE	30	O8PU	<p>xD-Picture Card Write Enable</p> <p>This pin is an active low write strobe signal for the xD-Picture Card device.</p> <p>When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET.</p> <p>If an external FET is used (internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).</p>
xD_nWP	29	O8PD	<p>xD-Picture Card Write Protect</p> <p>This pin is an active low write protect signal for the xD-Picture Card device. This pin has a weak pull-down resistor that is permanently enabled.</p>

# USB2660/USB2660i

**TABLE 4-1: USB2660/USB2660I PIN DESCRIPTIONS (CONTINUED)**

Symbol	64-PIN QFN	Buffer Type (Table 4-2)	Description
<b>USB INTERFACE</b>			
USBUP_DM USBUP_DP	59 58	I/O-U	USB Bus Data  These pins connect to the upstream USB bus data signals (host port or upstream hub). USBUP_DM and USBUP_DP can be swapped using the PortSwap feature (See <a href="#">Section 6.4.4.20, "F1h: Port Swap," on page 38</a> ).
USBDN_DM [3:2] USBDN_DP [3:2]	3 1 4 2	I/O-U	USB Bus Data  These pins connect to the downstream USB bus data signals and can be swapped using the PortSwap feature (See <a href="#">Section 6.4.4.20, "F1h: Port Swap," on page 38</a> ).
PRTCTL[3:2]	7 6	I/OD6 PU	USB Power Enable  As an output, these pins enable power to downstream USB peripheral devices and have weak internal pull-up resistors. See <a href="#">Section 4.3, "Port Power Control"</a> for diagram and usage instructions.  As an input, when the power is enabled, these pins monitor the over-current condition. When an over-current condition is detected, the pins turn the power off.
VBUS_DET	55	I	Detect Upstream VBUS Power  Detects the state of upstream VBUS power. The hub monitors VBUS_DET to determine when to assert the internal D+ pull-up resistor (signaling a connect event).  When designing a detachable hub, connect this pin to the VBUS power pin of the USB port that is upstream of the hub.  For self-powered applications with a permanently attached host, this pin should be pulled up, typically to VDD33.  VBUS is a 3.3 volt input. A resistor divider must be used if connecting to 5 volts of USB power.
RBIAS	63	I-R	USB Transceiver Bias  A 12.0 k $\Omega$ , $\pm$ 1.0% resistor is attached from VSS to this pin in order to set the transceiver's internal bias currents.
XTAL1 (CLKIN)	61	ICLKx	24 MHz Crystal Input or External Clock Input  This pin can be connected to one terminal of the crystal or it can be connected to an external 24 MHz clock when a crystal is not used.
XTAL2	60	OCLKx	24 MHz Crystal Output  This is the other terminal of the crystal, or it is left open when an external clock source is used to drive XTAL1(CLKIN).
<b>SPI INTERFACE</b>			
SPI_CE_n	49	O12	SPI Chip Enable  This is the active low chip enable output. If the SPI interface is enabled, this pin must be driven high in power down states.
SPI_CLK SCL	50	I/O12	This is the SPI clock out to the serial ROM. See <a href="#">Section 4.4, "ROM BOOT Sequence"</a> for diagram and usage instructions. During reset, drive this pin low.
		I/O6	When configured, this is the I <sup>2</sup> C EEPROM clock pin.

**TABLE 4-1: USB2660/USB2660I PIN DESCRIPTIONS (CONTINUED)**

Symbol	64-PIN QFN	Buffer Type (Table 4-2)	Description
SPI_DO / SDA / SPI_SPD_SEL	51	I/O12	This is the data out for the SPI port. See <a href="#">Section 4.4, "ROM BOOT Sequence"</a> for diagram and usage instructions.
		I/O6	This pin is the data pin when the device is connected to the optional I <sup>2</sup> C EEPROM.
		I/O12	This pin is used to select the speed of the SPI interface. During nRESET assertion, this pin will be tri-stated with the weak pull-down resistor enabled. When nRESET is negated, the value on the pin will be internally latched, and the pin will revert to SPI_DO functionality, the internal pull-down will be disabled.  '0' = 30 MHz (No external resistor should be applied.) '1' = 60 MHz (A 10 K external pull-up resistor must be applied.)  If the latched value is '1', then the pin is tri-stated when the chip is in the suspend state.  If the latched value is '0', then the pin is driven low during a suspend state.
SPI_DI	52	I/O12PD	This is the data in to the controller from the ROM. This pin has a weak internal pull-down applied at all times to prevent floating.
<b>MISC</b>			
LED	53	I/O6	It can be used as an LED output.
NC	44		
CRD_PWR2	15	I/O200	Card power drive: 3.3 V (100 mA or 200 mA)  This pin specifically powers the second Secure Digital interface (slot).  Please reference <a href="#">Section 6.4.5.9, "147h-14Bh: Device to LUN Mapping,"</a> on page 42.
CRD_PWR1	43	I/O200	Card power drive: 3.3 V (100 mA or 200 mA)  This pin powers the multiplexed flash media interface (slot) for xD, MS, and SD/MMC.  Please reference <a href="#">Section 6.4.2.3, "A4h-A5h: Smart Media Device Power Configuration,"</a> on page 30.
REG_EN		IPU	REG_EN: This pin is internally pulled up to enable the internal 1.8 V regulators.  In order to disable the regulators, this pin will need to be externally connected to ground.  When the internal regulator is enabled, the 1.8 V power pins must be left unconnected, except for the required bypass capacitors.
nRESET	54	IS	RESET Input  The system uses this active low signal reset the chip. The active low pulse should be at least 1 μs wide.
TEST	56	I	TEST Input  Tie this pin to ground for normal operation.

# USB2660/USB2660i

TABLE 4-1: USB2660/USB2660I PIN DESCRIPTIONS (CONTINUED)

Symbol	64-PIN QFN	Buffer Type (Table 4-2)	Description
<b>DIGITAL / POWER / GROUND</b>			
CRFILT	23		VDD Core Regulator Filter Capacitor This pin requires a 1.0 $\mu$ F (or greater) $\pm$ 20% (ESR <0.1 $\Omega$ ) capacitor to VSS.
PLLFILT	62		Phase-locked Loop Regulator Filter Capacitor This pin requires 1.0 $\mu$ F (or greater) $\pm$ 20% (ESR <0.1 $\Omega$ ) capacitor to VSS.
VDD33	5 14 24 33 42 47 57 64		3.3 V Power and Regulator Input Please refer to <a href="#">Section 8.0, "DC Parameters," on page 47</a> for more information. Pins 24 and 64 require external bypass capacitors of 4.7 $\mu$ F minimum.
VSS	ePad		The ground pad is the only VSS for the device and must be tied to ground with multiple vias.
NC	46 48		No Connect pins No trace or signal should be routed/attached to these pins.

## 4.2 Buffer Type Descriptions

TABLE 4-2: USB2660/USB2660I BUFFER TYPE DESCRIPTIONS

Buffer	Description
I	Input.
IPU	Input with weak internal pull-up.
IS	Input with Schmitt trigger.
I/O6	Input/output buffer with 6 mA sink and 6 mA source.
I/OD6PU	Input/open drain output buffer with a 6 mA sink.
O8	Output buffer with an 8 mA sink and an 8 mA source.
O8PD	Output buffer with an 8 mA sink and an 8 mA source with a weak internal pull-down resistor.
O8PU	Output buffer with an 8 mA sink and an 8 mA source with a weak internal pull-up resistor.
I/O8	Input/output buffer with an 8 mA sink and an 8 mA source.
I/O8PD	Input/output buffer with an 8 mA sink and an 8 mA source with a weak internal pull-down resistor.
I/O8PU	Input/output buffer with an 8 mA sink and an 8 mA source with a weak internal pull-up resistor.
O12	Output buffer with a 12 mA sink and a 12 mA source.
I/O12	Input/output buffer with 12 mA sink and 12 mA source.
I/O12PD	Input/output buffer with 12 mA sink and 12 mA source with a weak internal pull-down resistor.
I/O200	Input/output buffer 12 mA with FET disabled, 100/200 mA source only when the FET is enabled.
ICLKx	XTAL clock input.
OCLKx	XTAL clock output.
I/O-U	Analog input/output as defined in the USB 2.0 Specification.
I-R	RBIAS.

## 4.3 Port Power Control

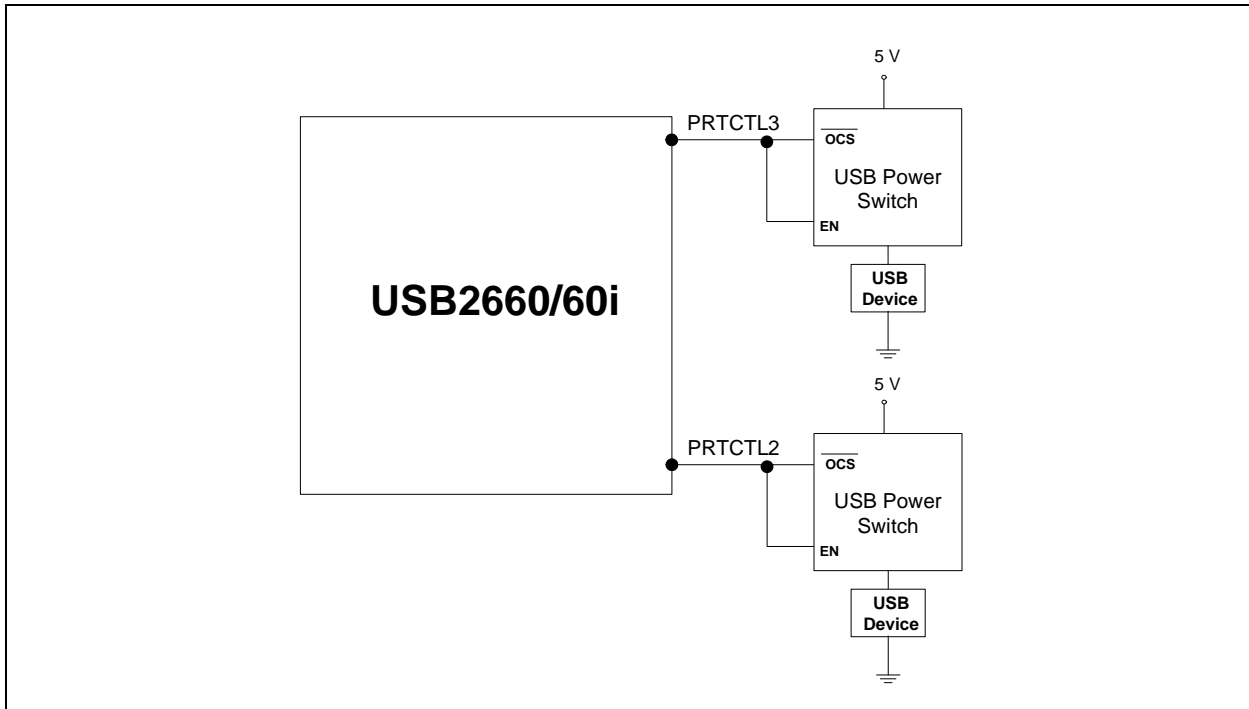
Port Power control using a USB Power Switch

The USB2660/USB2660i has a single port power control and over-current sense signal for each downstream port. When disabling port power, the driver will actively drive a '0'. To avoid unnecessary power dissipation, the internal pull-up resistor will be disabled at that time. When port power is enabled, the output driver is disabled, and the pull-up resistor is enabled creating an open drain output.

If there is an over-current situation, the USB Power Switch will assert the open drain OCS signal. The Schmitt trigger input will detect this event as a low. The open drain output does not interfere. The internal over-current sense filter handles the transient conditions, such as low voltage, while the device is powering up.

# USB2660/USB2660i

FIGURE 4-1: PORT POWER CONTROL WITH USB POWER SWITCH

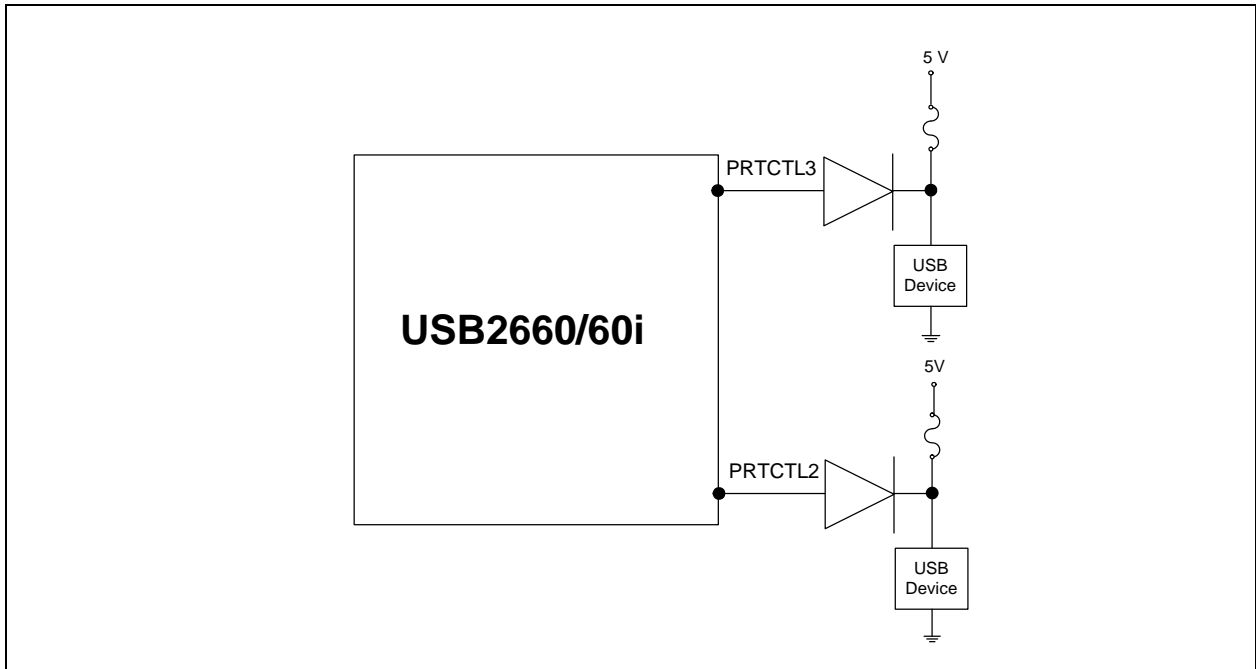


## 4.3.1 PORT POWER CONTROL USING A POLY FUSE

When using the USB2660/USB2660i with a poly fuse, an external diode must be used (See [Figure 4-2](#)). When disabling port power, the USB2660/USB2660i will drive a '0'. This procedure will have no effect since the external diode will isolate the pin from the load. When port power is enabled, the USB2660/USB2660i output driver is disabled, and the pull-up resistor is enabled which creates an open drain output. This open drain output condition means that the pull-up resistor is providing 3.3 volts to the anode of the diode. If there is an over-current situation, the poly fuse will open. This will cause the cathode of the diode to go to zero volts. The anode of the diode will be at 0.7 volts, and the Schmitt trigger input will register this as a low resulting in an over-current detection. The open drain output does not interfere.

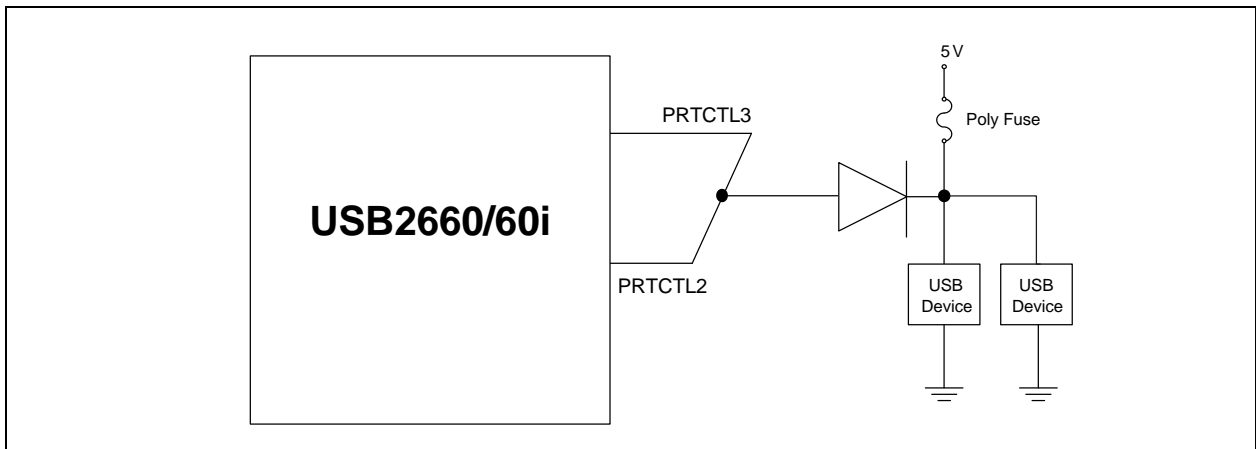


**FIGURE 4-2: PORT POWER CONTROL WITH A SINGLE POLY FUSE AND MULTIPLE LOADS**



When using a single poly fuse to power all devices, note that for the ganged situation, all power control pins must be tied together.

**FIGURE 4-3: PORT POWER WITH GANGED CONTROL WITH POLY FUSE**



# USB2660/USB2660i

## 4.4 ROM BOOT Sequence

After power-on reset, the internal firmware checks for an external SPI flash device that contains a valid signature of "2DFU" (device firmware upgrade) beginning at address 0xFFFFA. If a valid signature is found, then the external ROM is enabled and code execution begins at address 0x0000 in the external SPI device. Otherwise, code execution continues from the internal ROM.

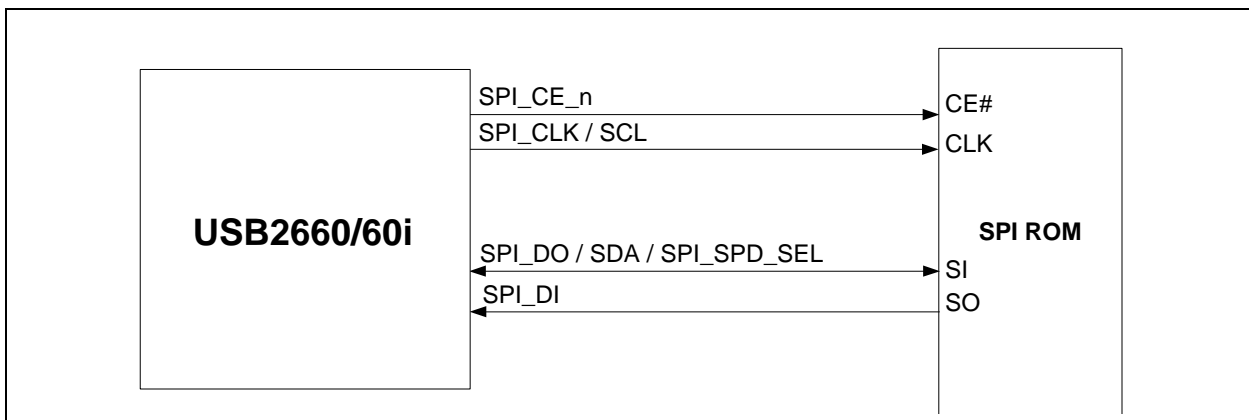
If there is no SPI ROM detected, the internal firmware then checks for the presence of an I<sup>2</sup>C ROM. The firmware looks for the signature 'ATA2' at the offset of FCh-FFh and 'ecf1' at the offset of 17Ch-17Fh in the I<sup>2</sup>C ROM. The firmware reads in the I<sup>2</sup>C ROM to configure the hardware and software internally. Please refer to [Section 6.3.2, "EEPROM Data Descriptor,"](#) on page 23 for the details of the configuration options.

The SPI ROM required for the USB2660/USB2660i is a recommended minimum of 1 Mbit and support either 30 MHz or 60 MHz. The frequency used is set using the SPI\_SPD\_SEL. For 30 MHz operation, this pin must be pulled to ground through a 100 kΩ resistor. For 60 MHz operation, this pin must pulled up through a 100 kΩ resistor.

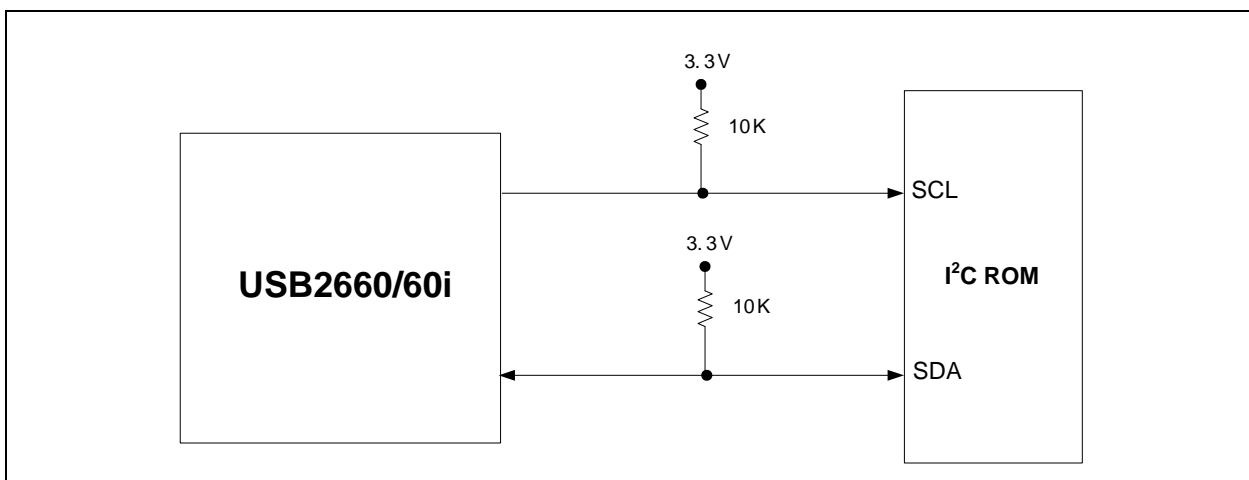
The SPI\_SPD\_SEL pin is used to choose the speed of the SPI interface. During nRESET assertion, this pin will be tri-stated with the weak pull-down resistor enabled. When nRESET is negated, the value on the pin will be internally latched, and the pin will revert to SPI\_DO functionality. The internal pull-down will be disabled.

The firmware can determine the speed of operation on the SPI port by checking the SPI\_SPEED in the SPI\_CTL register (0x2400 - RESET = 0x02). Both 1- and 2-bit SPI operation is supported. For optimum throughput, a 2-bit SPI ROM is recommended. Both mode 0 and mode 3 SPI ROMS are also supported.

**FIGURE 4-4: SPI ROM CONNECTION**



**FIGURE 4-5: I<sup>2</sup>C CONNECTION**



## 5.0 PIN RESET STATES

FIGURE 5-1: PIN RESET STATES

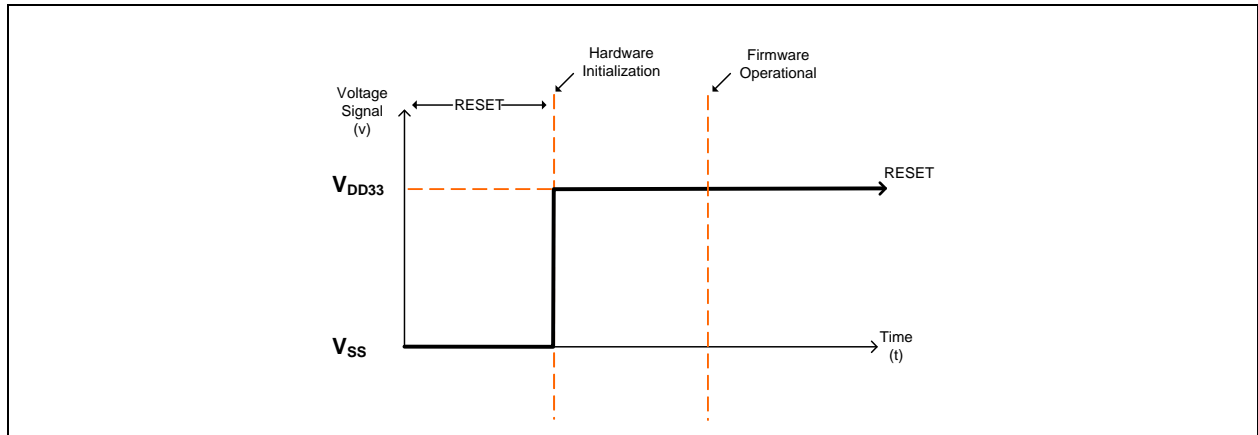


TABLE 5-1: LEGEND FOR PIN RESET STATES TABLE

Symbol	Description
0	Output driven low
1	Output driven high
IP	Input enabled
PU	Hardware enables pull-up
PD	Hardware enables pull-down
none	Hardware disables pad
--	Hardware disables function
Z	Hardware disables pad. Both output driver and input buffers are disabled.

### 5.1 Pin Reset States

TABLE 5-2: USB2660/USB2660I RESET STATES TABLE

Pin	Pin Name	Reset State		
		Function	Input/Output	PU/PD
1	USBDN_DM2	USBDN_DM2	IP	PD
2	USBDN_DP2	USBDN_DP2	IP	PD
3	USBDN_DM3	USBDN_DM3	IP	PD
4	USBDN_DP3	USBDN_DP3	IP	PD
6	PRTCTL2	PRTCTL	0	--
7	PRTCTL3	PRTCTL	0	--
8	SD2_nCD	none	IP	PU
9	SD2_D1	SD2_D1	Z	--

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TABLE 5-2: USB2660/USB2660I RESET STATES TABLE (CONTINUED)

Pin	Pin Name	Reset State		
		Function	Input/ Output	PU/PD
10	SD2_D0	SD2_D0	Z	--
11	SD2_D7	SD2_D7	Z	--
12	SD2_D6	SD2_D6	Z	--
13	SD2_CLK	SD2_CLK	Z	--
15	CRD_PWR2	none	Z	--
16	SD2_D5	SD2_D5	Z	--
17	SD2_CMD	SD2_CMD	Z	--
18	SD2_D4	SD2_D4	Z	--
19	SD2_D3	SD2_D3	Z	--
20	SD2_D2	SD2_D2	Z	--
21	SD1_WP / MS_SCLK / xD_D4	none	0	--
22	SD1_nCD	none	IP	PU
25	SD1_D1 / MS_D5 / xD_D3	none	Z	--
26	SD1_D0 / MS_D4 / xD_D2	none	Z	--
27	SD1_D7 / MS_D6 / xD_D1	none	Z	--
28	SD1_D6 / MS_D7 / xD_D0	none	Z	--
29	SD1_CLK / MS_BS / xD_nWP	none	Z	--
30	xD_nWE	xD_nWE	Z	--
31	SD1_D5 / MS_D1 / xD_ALE	none	Z	--
32	SD1_CMD / MS_D0 / xD_CLE	none	Z	--
34	xD_nCE	xD_nCE	Z	--
35	xD_nRE	xD_nRE	Z	--
36	xD_nB/R	xD_nB/R	Z	--
37	xD_nCD	none	IP	PU
38	SD1_D4 / MS_D2 / xD_D7	none	Z	--
39	MS_INS	none	IP	PU
40	SD1_D3 / MS_D3 / xD_D6	none	Z	--

**TABLE 5-2: USB2660/USB2660I RESET STATES TABLE (CONTINUED)**

Pin	Pin Name	Reset State		
		Function	Input/ Output	PU/PD
41	SD1_D2 / xD_D5	none	Z	--
43	CRD_PWR1	none	Z	--
44	NC	none	0	--
45	SD2_WP	none	0	--
49	SPI_CE_n	SPI_CE_n	1	--
50	SPI_CLK / SCL	none	0	--
51	SPI_DO / SDA / SPI_SPD_SEL	none	0	--
52	SPI_DI	SPI_DI	IP	PD
53	LED / TXD	none	0	--
54	nRESET	nRESET	IP	--
55	VBUS_DET	VBUS_DET	IP	--
56	TEST	TEST	IP	PD
58	USBUP_DP	USBUP_DP	Z	--
59	USBUP_DM	USBUP_DM	Z	--

# USB2660/USB2660i

---

## 6.0 CONFIGURATION OPTIONS

### 6.1 Hub

Microchip's USB 2.0 hub is fully compliant to the Universal Serial Bus Specification available from the USB Implementer's Forum found at <http://www.usb.org> (Revision 2.0 April 27, 2000 and the 12/7/2000 and 5/28/2002 Errata). Please reference Chapter 11 (Hub Specification) for general details regarding hub operation and functionality.

For performance reasons, the hub provides 1 transaction translator (TT) that is shared by both downstream ports defined as a single-TT configuration. The TT contains 4 non-periodic buffers.

#### 6.1.1 HUB CONFIGURATION OPTIONS

The Microchip hub supports a large number of features (some are mutually exclusive), and must be configured in order to correctly function when attached to a USB host controller. There are two principal ways to configure the hub:

- via the internal default settings or
- by settings stored in an external EEPROM or SPI Flash device.

##### 6.1.1.1 Power Switching Polarity

The hub will only support active high power controllers.

##### 6.1.2 VBUS DETECT

According to Section 7.2.1 of the USB 2.0 Specification, a device cannot provide power to its D+ or D- pull-up resistors unless the upstream port's VBUS is in the asserted (powered) state. The VBUS\_DET pin on the hub monitors the state of the upstream VBUS signal and will not pull-up the D+ resistor if VBUS is not active. If VBUS goes from an active to an inactive state (not powered), the hub will remove power from the D+ pull-up resistor within 10 seconds.

### 6.2 Card Reader

The Microchip USB2660/USB2660i is fully compliant with the following flash media card reader specifications:

- Secure Digital 2.0 / MultiMediaCard 4.2
  - SD 2.0, HS-SD, HC-SD
  - TransFlash™ and reduced form factor media
  - 1/4/8 bit MMC 4.2
- Memory Stick 1.43
- Memory Stick Pro Format 1.02
- Memory Stick Pro-HG Duo Format 1.01
  - Memory Stick, MS Duo, HS-MS, MS Pro-HG, MS Pro
- Memory Stick Duo 1.10
- xD-Picture Card 1.2

### 6.3 System Configurations

#### 6.3.1 EEPROM/SPI INTERFACE

The USB2660/USB2660i can be configured via a 2-wire (I<sup>2</sup>C) EEPROM (512x8) or an external SPI flash device containing the firmware for the USB2660/USB2660i. If an external configuration device does not exist the internal default values will be used. If one of the external devices is used for configuration, the OEM can update the values through the USB interface. The hub will then "attach" to the upstream USB host.

The USBDM tool set is available in the USB264x Hub Card reader combo software release package. To download the software package from Microchip's website, please visit:

[http://www.microchip.com/search/searchapp/searchhome.aspx?id=2&q=mkt/CW\\_SFT\\_PUB.nsf/Agreements/OBJ+Hub+Card+Reader](http://www.microchip.com/search/searchapp/searchhome.aspx?id=2&q=mkt/CW_SFT_PUB.nsf/Agreements/OBJ+Hub+Card+Reader)

to go to the [OBJ Hub Card Reader Software Download Agreement](#). Review the license, and if you agree, check the "I agree" box and then select "Confirm". You will then be able to download USB264x Hub Card reader combo release package zip file containing the USBDM tool set.

Please note that the following applies to the system values and descriptions when used:

- N/A = Not applicable to this part
- Reserved = For internal use

## 6.3.2 EEPROM DATA DESCRIPTOR

**TABLE 6-1: INTERNAL FLASH MEDIA CONTROLLER CONFIGURATIONS**

Address	Register Name	Description	Internal Default Value
00h	USB_SER_LEN	USB Serial String Descriptor Length	1Ah
01h	USB_SER_TYP	USB Serial String Descriptor Type	03h
02h-19h	USB_SER_NUM	USB Serial Number	"000008264001" (See <a href="#">Note 6-1</a> )
1Ah-1Bh	USB_VID	USB Vendor Identifier	0424
1Ch-1Dh	USB_PID	USB Product Identifier	4040
1Eh	USB_LANG_LEN	USB Language String Descriptor Length	04h
1Fh	USB_LANG_TYP	USB Language String Descriptor Type	03h
20h	USB_LANG_ID_LSB	USB Language Identifier Least Significant Byte	09h (See <a href="#">Note 6-3</a> )
21h	USB_LANG_ID_MSB	USB Language Identifier Most Significant Byte	04h (See <a href="#">Note 6-3</a> )
22h	USB_MFR_STR_LEN	USB Manufacturer String Descriptor Length	10h
23h	USB_MFR_STR_TYP	USB Manufacturer String Descriptor Type	03h
24h-31h	USB_MFR_STR	USB Manufacturer String	"Generic" (See <a href="#">Note 6-1</a> )
32h-5Dh	Reserved	-	00h
5Eh	USB_PRD_STR_LEN	USB Product String Descriptor Length	30h
5Fh	USB_PRD_STR_TYP	USB Product String Descriptor Type	03h
60h-99h	USB_PRD_STR	USB Product String	"Ultra Fast Media Reader" (See <a href="#">Note 6-1</a> )
9Ah	USB_BM_ATT	USB BmAttribute	80h
9Bh	USB_MAX_PWR	USB Max Power	30h (96 mA)
9Ch	ATT_LB	Attribute Lo byte	40h (Reverse SD_WP only)
9Dh	ATT_HLB	Attribute Hi Lo byte	80h (Reverse SD2_WP only)
9Eh	ATT_LHB	Attribute Lo Hi byte	00h
9Fh	ATT_HB	Attribute Hi byte	00h
A0h	MS_PWR_LB	Memory Stick Device Power Lo byte	00h
A1h	MS_PWR_HB	Memory Stick Device Power Hi byte	0Ah
A2h-A3h	Not Applicable	-	00h
A4h	SM_PWR_LB	Smart Media Device Power Lo byte	00h (See <a href="#">Note 6-2</a> )
A5h	SM_PWR_HB	Smart Media Device Power Hi byte	0Ah (See <a href="#">Note 6-2</a> )

# USB2660/USB2660i

**TABLE 6-1: INTERNAL FLASH MEDIA CONTROLLER CONFIGURATIONS (CONTINUED)**

Address	Register Name	Description	Internal Default Value
A6h	SD_PWR_LB	Secure Digital Device Power Lo byte	00h
A7h	SD_PWR_HB	Secure Digital Device Power Hi byte	0Ah
A8h	LED_BLK_INT	LED Blink Interval	02h
A9h	LED_BLK_DUR	LED Blink After Access	28h
AAh - B0h	DEV0_ID_STR	Device 0 Identifier String	N/A
B1h - B7h	DEV1_ID_STR	Device 1 Identifier String	"MS"
B8h - BEh	DEV2_ID_STR	Device 2 Identifier String	"SM" (See <a href="#">Note 6-2</a> )
BFh - C5h	DEV3_ID_STR	Device 3 Identifier String	"SD/MMC"
C6h - CDh	INQ_VEN_STR	Inquiry Vendor String	"Generic"
CEh - D2h	INQ_PRD_STR	Inquiry Product String	82660
D3h	DYN_NUM_LUN	Dynamic Number of LUNs	01h
D4h - D7h	DEV_LUN_MAP	Device to LUN Mapping	FFh, 00h, 00h, 00h
D8h - DAh	Reserved	-	00h, 06h, 0Dh
DBh - DDh	Reserved	-	59h, 56h, 97h

**TABLE 6-2: HUB CONTROLLER CONFIGURATIONS**

Address	Register Name	Description	Internal Default Value
DEh	VID_LSB	Vendor ID Least Significant Byte	24h
DFh	VID_MSB	Vendor ID Most Significant Byte	04h
E0h	PID_LSB	Product ID Least Significant Byte	60h
E1h	PID_MSB	Product ID Most Significant Byte	26h
E2h	DID_LSB	Device ID Least Significant Byte	A1h
E3h	DID_MSB	Device ID Most Significant Byte	08h
E4h	CFG_DAT_BYT1	Configuration Data Byte 1	8Bh
E5h	CFG_DAT_BYT2	Configuration Data Byte 2	28h
E6h	CFG_DAT_BYT3	Configuration Data Byte 3	00h
E7h	NR_DEVICE	Non-Removable Devices	02h
E8h	PORT_DIS_SP	Port Disable (Self)	00h
E9h	PORT_DIS_BP	Port Disable (Bus)	00h
EAh	MAX_PWR_SP	Max Power (Self)	01h
EBh	MAX_PWR_BP	Max Power (Bus)	32h
ECh	HC_MAX_C_SP	Hub Controller Max Current (Self)	01h
EDh	HC_MAX_C_BP	Hub Controller Max Current (Bus)	32h
EEh	PWR_ON_TIME	Power-on Time	32h
EFh	BOOST_UP	Boost_Up	00h
F0h	BOOST_3:0	Boost_3:0	00h
F1h	PRT_SWP	Port Swap	00h
F2h	PRTM12	Port Map 12	00h
F3h	PRTM3	Port Map 3	00h



**TABLE 6-3: OTHER INTERNAL CONFIGURATIONS**

Address	Register Name	Description	Internal Default Value
F4h	Reserved	Reserved	00h
F5h	Reserved	Reserved	66h
F6h	Reserved	Reserved	00h
F7h	Reserved	Reserved	00h
F8h-FAh	Reserved	Reserved	59h, 56h, 97h
FBh	Not Applicable	-	00h
FCh-FFh	NVSTORE_SIG	Non-Volatile Storage Signature	"ATA2"

## 6.4 Set bit 7 of bmAttribute to enable the registers in Table 6-4.

**TABLE 6-4: INTERNAL FLASH MEDIA CONTROLLER EXTENDED CONFIGURATIONS**

Address	Register Name	Description	Internal Default Value
100h - 106h	CLUN0_ID_STR	Combo LUN 0 Identifier String	"COMBO"
107h - 10Dh	CLUN1_ID_STR	Combo LUN 1 Identifier String	"COMBO"
10Eh - 114h	CLUN2_ID_STR	Combo LUN 2 Identifier String	"COMBO"
115h - 11Bh	CLUN3_ID_STR	Combo LUN 3 Identifier String	"COMBO"
11Ch - 122h	CLUN4_ID_STR	Combo LUN 4 Identifier String	"COMBO"
123h - 129h	DEV4_ID_STR	Device 4 Identifier String	"SD/MMC2"
12Ah-145h	Not applicable	-	00h
12Ah - 130h			00h
131h - 137h			00h
138h - 13Eh			00h
13Fh - 145h			00h
146h	DYN_NUM_EXT_LUN	Dynamic Number of Extended LUNs	01h
147h - 14Bh	DEV_LUN_MAP	Device to LUN Mapping	01h, FFh, FFh, FFh, FFh
14Ch	SD2_PWR_LB	Second Secure Digital Power Lo byte-	0Ah
14Dh	SD2_PWR_HB	Second Secure Digital Power Hi byte	00h
14Eh-17Bh	Not Applicable	-	00h
17Ch-17Fh	NVSTORE_SIG2	Non-Volatile Storage Signature	"ecf1"

**Note 6-1** This value is a UNICODE UTF-16LE encoded string value that meets the USB 2.0 specification (Revision 2.0, 2000). Values in double quotations without this note are ASCII values.

**Note 6-2** A value of "SM" will be overridden with "xD" once an xD-Picture Card has been identified.

**Note 6-3** For a list of the most current 16-bit language ID's defined by the USB-IF, please visit <http://www.unicode.org> or consult *The Unicode Standard, Worldwide Character Encoding*, (Version 4.0), The Unicode Consortium, Addison-Wesley Publishing Company, Reading, Massachusetts.

# USB2660/USB2660i

## 6.4.1 EEPROM DATA DESCRIPTOR REGISTER DESCRIPTIONS

### 6.4.1.1 00h: USB Serial String Descriptor Length

Byte	Name	Description
0	USB_SER_LEN	USB serial string descriptor length as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bLength” which describes the size of the string descriptor (in bytes).

### 6.4.1.2 01h: USB Serial String Descriptor Type

Byte	Name	Description
1	USB_SER_TYP	USB serial string descriptor type as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bDescriptorType” which is a constant value associated with a string descriptor type.

### 6.4.1.3 02h-19h: USB Serial Number Option

Byte	Name	Description
25:2	USB_SER_NUM	Maximum string length is 12 hex digits. Must be unique to each device.

### 6.4.1.4 1Ah-1Bh: USB Vendor ID Option

Byte	Name	Description
1:0	USB_VID	This ID is unique for every vendor. The vendor ID is assigned by the USB Implementer’s Forum.

### 6.4.1.5 1Ch-1Dh: USB Product ID Option

Byte	Name	Description
1:0	USB_PID	This ID is unique for every product. The product ID is assigned by the vendor.

### 6.4.1.6 1Eh: USB Language Identifier Descriptor Length

Byte	Name	Description
0	USB_LANG_LEN	USB language ID string descriptor length as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bLength” which describes the size of the string descriptor (in bytes).

### 6.4.1.7 1Fh: USB Language Identifier Descriptor Type

Byte	Name	Description
1	USB_LANG_TYP	USB language ID string descriptor type as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bDescriptorType” which is a constant value associated with a string descriptor type.

### 6.4.1.8 20h: USB Language Identifier Least Significant Byte

Byte	Name	Description
2	USB_LANG_ID_LSB	English language code = ‘0409’. See <a href="#">Note 6-3</a> to reference additional language ID’s defined by the USB-IF.

## 6.4.1.9 21h: USB Language Identifier Most Significant Byte

Byte	Name	Description
3	USB_LANG_ID_MSB	English language code = '0409'. See <a href="#">Note 6-3</a> to reference additional language ID's defined by the USB-IF.

## 6.4.1.10 22h: USB Manufacturer String Descriptor Length

Byte	Name	Description
0	USB_MFR_STR_LEN	USB manufacturer string descriptor length as defined by Section 9.6.7 "String" of the USB 2.0 Specification (Revision 2.0, 2000). This field is the "bLength" which describes the size of the string descriptor (in bytes).

## 6.4.1.11 23h: USB Manufacturer String Descriptor Type

Byte	Name	Description
1	USB_MFR_STR_TYP	USB manufacturer string descriptor type as defined by Section 9.6.7 "String" of the USB 2.0 Specification (Revision 2.0, 2000). This field is the "bDescriptorType" which is a constant value associated with a string descriptor type.

## 6.4.1.12 24h-31h: USB Manufacturer String Option

Byte	Name	Description
15:2	USB_MFR_STR	The maximum string length is 28 characters.

## 6.4.1.13 32h-5Dh: Reserved

Byte	Name	Description
59:16	Reserved	Reserved.

## 6.4.1.14 5Eh: USB Product String Descriptor Length

Byte	Name	Description
0	USB_PRD_STR_LEN	USB product string descriptor length as defined by Section 9.6.7 "String" of the USB 2.0 Specification (Revision 2.0, 2000). This field is the "bLength" which describes the size of the string descriptor (in bytes).

## 6.4.1.15 5Fh: USB Product String Descriptor Type

Byte	Name	Description
1	USB_PRD_STR_TYP	USB product string descriptor type as defined by Section 9.6.7 "String" of the USB 2.0 Specification (Revision 2.0, 2000). This field is the "bDescriptorType" which is a constant value associated with a string descriptor type.

## 6.4.1.16 60h-99h: USB Product String Option

Byte	Name	Description
59:2	USB_PRD_STR	This string will be used during the USB enumeration process in the Windows <sup>®</sup> operating system. Maximum string length is 28 characters.

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## 6.4.1.17 9Ah: USB BmAttribute (1 byte)

Bit	Name	Description
7:0	USB_BM_ATT	<p>Self- or Bus-Power: Selects between self- and bus-powered operation.</p> <p>The hub is either self-powered (draws less than 2 mA of upstream bus power) or bus-powered (limited to a 100 mA maximum of upstream power prior to being configured by the host controller).</p> <p>When configured as a bus-powered device, the Microchip hub consumes less than 100 mA of current prior to being configured. After configuration, the bus-powered Microchip hub (along with all associated hub circuitry, any embedded devices if part of a compound device, and 100 mA per externally available downstream port) must consume no more than 500 mA of upstream VBUS current. The current consumption is system dependent, and the OEM must ensure that the USB 2.0 Specification is not violated.</p> <p>When configured as a self-powered device, &lt;1 mA of upstream VBUS current is consumed and all ports are available, with each port being capable of sourcing 500 mA of current.</p> <p><b>80 = Bus-powered operation (default)</b> C0 = Self-powered operation A0 = Bus-powered operation with remote wake-up E0 = Self-powered operation with remote wake-up</p>

## 6.4.1.18 9Bh: USB MaxPower (1 byte)

Bit	Name	Description
7:0	USB_MAX_PWR	USB Max Power per the USB 2.0 Specification. Do NOT set this value greater than 100 mA.

## 6.4.1.19 9Ch-9Fh: Attribute Byte Descriptions

Byte	Byte Name	Bit	Description
0	ATT_LB	3:0	Always reads '0'.
		4	Inquire Manufacturer and Product ID Strings '1' - Use the Inquiry Manufacturer and Product ID Strings. '0' (default) - Use the USB Descriptor Manufacturer and Product ID Strings.
		5	Always reads '0'.
		6	Reverse SD Card Write Protect Sense '1' (default) - SD cards will be write protected when SW_nWP is high, and writable when SW_nWP is low. '0' - SD cards will be write protected when SW_nWP is low, and writable when SW_nWP is high.
		7	Extended Configuration Enable '1' - This bit must be set to '1' to enable editing, updating, and reading from registers 100h-17Fh. '0' - The internal configuration is loaded. When this bit is not set (and it equals '0'). It will not read from registers 100h-17Fh.
1	ATT_HLB	3:0	Always reads '0'.
		4	Activity LED True Polarity '1' - Activity LED to Low True. '0' (default) - Activity LED polarity to High True.
		5	Common Media Insert / Media Activity LED '1' - The activity LED will function as a common media inserted/media access LED. '0' (default) - The activity LED will remain in its idle state until media is accessed.
		6	Always reads '0'.
		7	Reverse SD2 Card Write Protect Sense '1' (default) - SD cards in LUN 1 will be write protected when SW_nWP is high, and writable when SW_nWP is low. '0' - SD cards in LUN 1 will be write protected when SW_nWP is low, and writable when SW_nWP is high.
2	ATT_LHB	0	Attach on Card Insert / Detach on Card Removal '1' - Attach on Insert is enabled. '0' (default) - Attach on Insert is disabled.
		1	Always reads '0'.
		2	Enable Device Power Configuration '1' - Custom Device Power Configuration stored in the NVSTORE is used. '0' (default) - Default Device Power Configuration is used.
		7:3	Always reads '0'.
3	ATT_HB	6:0	Always reads '0'.
		7	xD Player Mode

# USB2660/USB2660i

## 6.4.2 A0H-A7H: DEVICE POWER CONFIGURATION

The USB2660/USB2660i has two internal FETs which can be utilized for card power. For information about the other internal FET, please see [Section 6.4.5.10, "14Ch-14Dh: Second Secure Digital Device Power Configuration," on page 42](#). This section describes the default internal configuration. The settings are stored in NVSTORE and provide the following features:

1. A card can be powered by an external FET or by an internal FET.
2. The power limit can be set to 100 mA or 200 mA (Default) for the internal FET.

Each media uses two bytes to store its device power configuration. Bit 3 selects between internal or external card power FET options. For internal FET card power control, bits 0 through 2 are used to set the power limit. The "Device Power Configuration" bits are ignored unless the "Enable Device Power Configuration" bit is set. See [Section 6.4.1.19, "9Ch-9Fh: Attribute Byte Descriptions," on page 29](#).

### 6.4.2.1 A0h-A1h: Memory Stick Device Power Configuration

FET	Type	Bits	Bit Type	Description
0	FET Lo Byte MS_PWR_LB	3:0	Low Nibble	0000b Disabled
1		7:4	High Nibble	
2	FET Hi Byte MS_PWR_HB	3:0	Low Nibble	0000b Disabled 0001b External FET enabled 1000b Internal FET with 100 mA power limit <b>1010b Internal FET with 200 mA power limit</b>
3			7:4	

### 6.4.2.2 A2h-A3h: Not Applicable

Byte	Name	Description
1:0	Not Applicable	Not applicable.

### 6.4.2.3 A4h-A5h: Smart Media Device Power Configuration

FET	Type	Bits	Bit Type	Description
0	FET Lo Byte SM_PWR_LB	3:0	Low Nibble	0000b Disabled
1		7:4	High Nibble	
2	FET Hi Byte SM_PWR_HB	3:0	Low Nibble	0000b Disabled 0001b External FET enabled 1000b Internal FET with 100 mA power limit <b>1010b Internal FET with 200 mA power limit</b>
3			7:4	

### 6.4.2.4 A6h-A7h: Secure Digital Device Power Configuration

FET	Type	Bits	Bit Type	Description
0	FET Lo Byte SD_PWR_LB	3:0	Low Nibble	0000b Disabled
1		7:4	High Nibble	
2	FET Hi Byte SD_PWR_HB	3:0	Low Nibble	0000b Disabled 0001b External FET enabled 1000b Internal FET with 100 mA power limit <b>1010b Internal FET with 200 mA power limit</b>
3			7:4	

## 6.4.2.5 A8h: LED Blink Interval

Byte	Name	Description
0	LED_BLK_INT	The blink rate is programmable in 50 ms intervals. The high bit (7) indicates an idle state:  '0' - Off '1' - On  The remaining bits (6:0) are used to determine the blink interval up to a max of 128 x 50 ms.

## 6.4.2.6 A9h: LED Blink Duration

Byte	Name	Description
1	LED_BLK_DUR	LED Blink After Access. This byte is used to designate the number of seconds that the LED will continue to blink after a drive access. Setting this byte to "05" will cause the LED to blink for 5 seconds after a drive access.

## 6.4.3 DEVICE ID STRINGS

These bytes are used to specify the LUN descriptor returned by the device. These bytes are used in combination with the device to LUN mapping bytes in applications where the OEM wishes to reorder and rename the LUNs. If multiple devices are mapped to the same LUN (a COMBO LUN), then the CLUN#\_ID\_STR will be used to name the COMBO LUN instead of the individual device strings. When applicable, the "SM" value will be overridden with xD once an xD-Picture Card has been identified.

### 6.4.3.1 AAh-B0h: Device 0 Identifier String

Byte	Name	Description
6:0	DEV0_ID_STR	Not applicable.

### 6.4.3.2 B1h-B7h: Device 1 Identifier String

Byte	Name	Description
6:0	DEV1_ID_STR	This ID string is associated with the Memory Stick device.

### 6.4.3.3 B8h-BEh: Device 2 Identifier String

Byte	Name	Description
6:0	DEV2_ID_STR	This ID string is associated with the Smart Media (Note 6-2) device.

### 6.4.3.4 BFh-C5h: Device 3 Identifier String

Byte	Name	Description
6:0	DEV3_ID_STR	This ID string is associated with the Secure Digital / MultiMediaCard device.

### 6.4.3.5 C6h-CDh: Inquiry Vendor String

Byte	Name	Description
7:0	INQ_VEN_STR	If bit 4 of the 1st attribute byte is set, the device will use these strings in response to a USB inquiry command, instead of the USB descriptor manufacturer and product ID strings.

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## 6.4.3.6 CEh-D2h: Inquiry Product String

Byte	Name	Description
4:0	INQ_PRD_STR	If bit 4 of the 1st attribute byte is set, the device will use these strings in response to a USB inquiry command, instead of the USB descriptor manufacturer and product ID strings.

## 6.4.3.7 D3h: Dynamic Number of LUNs

Byte	Name	Description
7:0	DYN_NUM_LUN	<p>These bytes are used to specify the number of LUNs the device exposes to the host. These bytes are also used for icon sharing by assigning more than one LUN to a single icon. This is used in applications where the device utilizes a combo socket and the OEM wishes to have only a single icon displayed for one or more interfaces.</p> <p>If this field is set to "FF", the program assumes that you are using the default value and icons will be configured per the default configuration.</p>

## 6.4.3.8 D4h-D7h: Device to LUN Mapping

Byte	Name	Description
3:0	DEV_LUN_MAP	<p>These registers map a device controller (SD/MMC, SM (Note 6-2), and MS) to a Logical Unit Number (LUN). The device reports the mapped LUNs to the USB host in the USB descriptor during enumeration. The icon installer associates custom icons with the LUNs specified in these fields.</p> <p>Setting a register to "FF" indicates that the device is not mapped. Setting all of the DEV_LUN_MAP registers for all devices to "FF" forces the use of the default mapping configuration. Not all configurations are valid. Valid configurations depend on the hardware, packaging, and OEM board layout. The number of unique LUNs mapped must match the value in the <a href="#">Section 6.4.3.7, "D3h: Dynamic Number of LUNs," on page 32.</a></p>

## 6.4.3.9 D8h-DDh: Reserved

Byte	Name	Description
2:0	Reserved	Reserved.

## 6.4.4 HUB CONTROLLER CONFIGURATIONS

### 6.4.4.1 DEh: Vendor ID (LSB)

Bit	Byte Name	Description
7:0	VID_LSB	Least Significant Byte of the Vendor ID. This is a 16-bit value that uniquely identifies the vendor of the user device (assigned by USB Implementer's Forum).

### 6.4.4.2 DFh: Vendor ID (MSB)

Bit	Byte Name	Description
7:0	VID_MSB	Most Significant Byte of the Vendor ID. This is a 16-bit value that uniquely identifies the vendor of the user device (assigned by USB Implementer's Forum).



## 6.4.4.3 E0h: Product ID (LSB)

Bit	Name	Description
7:0	PID_LSB	Least Significant Byte of the Product ID. This is a 16-bit value that the vendor can assign that uniquely identifies this particular product.

## 6.4.4.4 E1h: Product ID (MSB)

Bit	Name	Description
7:0	PID_MSB	Most Significant Byte of the Product ID. This is a 16-bit value that the vendor can assign that uniquely identifies this particular product.

## 6.4.4.5 E2h: Device ID (LSB)

Bit	Name	Description
7:0	DID_LSB	Least Significant Byte of the Device ID. This is a 16-bit device release number in BCD (binary coded decimal) format.

## 6.4.4.6 E3h: Device ID (MSB)

Bit	Name	Description
7:0	DID_MSB	Most Significant Byte of the Device ID. This is a 16-bit device release number in BCD format.

## 6.4.4.7 E4h: Configuration Data Byte 1 (**CFG\_DAT\_BYT1**)

Bit	Name	Description
7	SELF_BUS_PWR	<p>Self- or Bus-Power: Selects between self- and bus-powered operation.</p> <p>The hub is either self-powered (draws less than 2 mA of upstream bus power) or bus-powered (limited to a 100 mA maximum of upstream power prior to being configured by the host controller).</p> <p>When configured as a bus-powered device, the Microchip hub consumes less than 100 mA of current prior to being configured. After configuration, the bus-powered Microchip hub (along with all associated hub circuitry, any embedded devices if part of a compound device, and 100 mA per externally available downstream port) must consume no more than 500 mA of upstream VBUS current. The current consumption is system dependent, and the OEM must ensure that the USB 2.0 specifications are not violated.</p> <p>When configured as a self-powered device, &lt;1 mA of upstream VBUS current is consumed and all ports are available, with each port being capable of sourcing 500 mA of current.</p> <p>'0' = Bus-powered operation '1' = Self-powered operation</p>
6	Reserved	Reserved
5	HS_DISABLE	<p>Hi-Speed Disable: Disables the capability to attach as either a Hi-/Full-Speed device, and forces attachment as Full-Speed only (i.e. no Hi-Speed support).</p> <p>'0' = Hi-/Full-Speed '1' = Full-Speed-Only (Hi-Speed disabled!)</p>
4	Reserved	Reserved

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Bit	Name	Description
3	EOP_DISABLE	<p>EOP Disable: Disables EOP generation of EOF1 when in Full-Speed mode. During FS operation only, this permits the hub to send EOP if no downstream traffic is detected at EOF1. See Section 11.3.1 of the USB 2.0 Specification for additional details.</p> <p>'0' = An EOP is generated at the EOF1 point if no traffic is detected. '1' = EOP generation at EOF1 is disabled (normal USB operation).</p> <p><b>Note:</b> Generation of an EOP at the EOF1 point may prevent a host controller (operating in FS mode) from placing the USB bus in suspend.</p>
2:1	CURRENT_SNS	<p>Over-Current Sense: Selects current sensing on a port-by-port basis, all ports ganged, or none (only for bus-powered hubs). The ability to support current sensing on a per port or ganged basis is dependent upon the hardware implementation.</p> <p>'00' = Ganged sensing (all ports together) '01' = Individual (port-by-port) '1x' = Over-current sensing not supported (must only be used with bus-powered configurations!)</p>
0	PORT_PWR	<p>Port Power Switching: Enables power switching on all ports simultaneously (ganged), or port power is individually switched on and off on a port-by-port basis (individual). The ability to support power enabling on a port or ganged basis is dependent upon the hardware implementation.</p> <p>'0' = Ganged switching (all ports together) '1' = Individual port-by-port switching</p>

## 6.4.4.8 E5h: Configuration Data Byte 2 (CFG\_DAT\_BYT2)

Bit	Name	Description
7:6	Reserved	Reserved
5:4	OC_TIMER	<p>OverCurrent Timer: Over-current timer delay.</p> <p>'00' = 50 ns '01' = 100 ns '10' = 200 ns '11' = 400 ns</p>
3	COMPOUND	<p>Compound Device: Allows OEM to indicate that the hub is part of a compound device (per the USB 2.0 Specification). The applicable port(s) must also be defined as having a "non-removable device".</p> <p><b>Note:</b> When configured via strapping options, declaring a port as non-removable automatically causes the hub controller to report that it is part of a compound device.</p> <p>'0' = No '1' = Yes, the hub is part of a compound device</p>
2:0	Reserved	Reserved

## 6.4.4.9 E6h: Configuration Data Byte 3 (CFG\_DAT\_BYT3)

Bit	Name	Description
7:4	Reserved	Reserved
3	PRTMAP_EN	<p>Port Mapping Enable: Selects the method used by the hub to assign port numbers and disable ports.</p> <p>'0' = Standard Mode. Strap options or the following registers are used to define which ports are enabled, and the ports are mapped as port 'n' on the hub is reported as port 'n' to the host, unless one of the ports is disabled, then the higher numbered ports are remapped in order to report contiguous port numbers to the host.</p> <p>Register 300Ah: Port disable for self-powered operation (Reset = 0x00). Register 300Bh: Port disable for bus-powered operation (Reset = 0x00).</p> <p>'1' = Port Map mode. The mode enables remapping via the registers defined below.</p> <p>Register 30FBh: Port Map 12 (Reset = 0x00) Register 30FCh: Port Map 3 (Reset = 0x00)</p>
2:0	Reserved	Reserved

## 6.4.4.10 E7h: Non-Removable Device

Bit	Byte Name	Description
7:0	NR_DEVICE	<p>Indicates which port(s) include non-removable devices.</p> <p>'0' = Port is removable '1' = Port is non-removable</p> <p>Informs the host if one of the active ports has a permanent device that is undetachable from the hub. The device must provide its own descriptor data.</p> <p>When using the internal default option, the NON_REM[1:0] pins will designate the appropriate ports as being non-removable.</p> <p>Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Controls physical port 1 Bit 0= Reserved</p> <p><b>Note:</b> Bit 1 must be set to a '1' by the firmware for proper identification of the card reader as a non-removable device.</p>

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## 6.4.4.11 E8h: Port Disable For Self-Powered Operation

Bit	Byte Name	Description
7:0	PORT_DIS_SP	<p>Disables 1 or more ports.</p> <p>'0' = Port is available '1' = Port is disabled</p> <p>During self-powered operation this register selects the ports which will be permanently disabled. The ports are unavailable to be enabled or enumerated by a host controller. The ports can be disabled in any order since the internal logic will automatically report the correct number of enabled ports to the USB host and will reorder the active ports in order to ensure proper function.</p> <p>Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Controls physical port 1 Bit 0= Reserved</p>

## 6.4.4.12 E9h: Port Disable For Bus-Powered Operation

Bit	Byte Name	Description
7:0	PORT_DIS_BP	<p>Disables 1 or more ports.</p> <p>'0' = Port is available '1' = Port is disabled</p> <p>During self-powered operation, this register selects the ports which will be permanently disabled. The ports are unavailable to be enabled or enumerated by a host controller. The ports can be disabled in any order, the internal logic will automatically report the correct number of enabled ports to the USB host and will reorder the active ports in order to ensure proper function.</p> <p>When using the internal default option, the PRT_DIS[1:0] pins will disable the appropriate ports.</p> <p>Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Controls physical port 1 Bit 0 is Reserved</p>

## 6.4.4.13 EAh: Max Power For Self-Powered Operation

Bit	Byte Name	Description
7:0	MAX_PWR_SP	<p>Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a self-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value also includes the power consumption of a permanently attached peripheral if the hub is configured as a compound device, and the embedded peripheral reports 0 mA in its descriptors.</p> <p><b>Note:</b> The USB 2.0 Specification does not permit this value to exceed 100 mA.</p>

## 6.4.4.14 EBh: Max Power For Bus-Powered Operation

Bit	Byte Name	Description
7:0	MAX_PWR_BP	Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a bus-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value also includes the power consumption of a permanently attached peripheral if the hub is configured as a compound device, and the embedded peripheral reports 0 mA in its descriptors.

## 6.4.4.15 ECh: Hub Controller Max Current For Self-Powered Operation

Bit	Byte Name	Description
7:0	HC_MAX_C_SP	Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a self-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value does NOT include the power consumption of a permanently attached peripheral if the hub is configured as a compound device.  <b>Note:</b> The USB 2.0 Specification does not permit this value to exceed 100 mA.  A value of 50 (decimal) indicates 100 mA, which is the default value.

## 6.4.4.16 EDh: Hub Controller Max Current For Bus-Powered Operation

Bit	Byte Name	Description
7:0	HC_MAX_C_BP	Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a bus-powered hub. This value will include the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value will NOT include the power consumption of a permanently attached peripheral if the hub is configured as a compound device.  A value of 50 (decimal) would indicate 100 mA, which is the default value.

## 6.4.4.17 EEh: Power-On Time

Bit	Byte Name	Description
7:0	PWR_ON_TIME	The length of time that it takes (in 2 ms intervals) from the time the host initiated power-on sequence begins on a port until power is adequate on that port. If the host requests the power-on time, the system software uses this value to determine how long to wait before accessing a powered-on port.

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## 6.4.4.18 EFh: Boost\_Up

Bit	Name	Description
7:2	Reserved	Reserved
1:0	BOOST_IOUT	<p>USB electrical signaling drive strength boost bit for the upstream port 'A'.</p> <p>'00' = Normal electrical drive strength = No boost            '01' = Elevated electrical drive strength = Low (approximately 4% boost)            '10' = Elevated electrical drive strength = Medium (approximately 8% boost)            '11' = Elevated electrical drive strength = High (approximately 12% boost)</p> <p><b>Note:</b> "Boost" could result in non-USB compliant parameters. OEM should use a '00' value unless specific implementation issues require additional signal boosting to correct for degraded USB signaling levels.</p>

## 6.4.4.19 F0h: Boost\_3:0

Bit	Name	Description
7:6	Reserved	Reserved
5:4	BOOST_IOUT_3	<p>Upstream USB electrical signaling drive strength boost bit for downstream port '3'.</p> <p>'00' = Normal electrical drive strength = No boost            '01' = Elevated electrical drive strength = Low (approximately 4% boost)            '10' = Elevated electrical drive strength = Medium (approximately 8% boost)            '11' = Elevated electrical drive strength = High (approximately 12% boost)</p>
3:2	BOOST_IOUT_2	<p>Upstream USB electrical signaling drive strength boost bit for downstream port '2'.</p> <p>'00' = Normal electrical drive strength = No boost            '01' = Elevated electrical drive strength = Low (approximately 4% boost)            '10' = Elevated electrical drive strength = Medium (approximately 8% boost)            '11' = Elevated electrical drive strength = High (approximately 12% boost)</p> <p><b>Note:</b> "Boost" could result in non-USB Compliant parameters. OEM should use a '00' value unless specific implementation issues require additional signal boosting to correct for degraded USB signaling levels.</p>
1:0	Reserved	Always reads '0'.

## 6.4.4.20 F1h: Port Swap

Bit	Byte Name	Description
7:0	PRT_SWP	<p>Swaps the upstream and downstream USB DP and DM pins for ease of board routing to devices and connectors.</p> <p>'0' = USB D+ functionality is associated with the DP pin and D- functionality is associated with the DM pin.</p> <p>'1' = USB D+ functionality is associated with the DM pin and D- functionality is associated with the DP pin.</p> <p>Bit 7= Reserved            Bit 6= Reserved            Bit 5= Reserved            Bit 4= Reserved            Bit 3= Controls physical port 3            Bit 2= Controls physical port 2            Bit 1= Reserved            Bit 0= Controls physical port 0</p>

## 6.4.4.21 F2h: Port Map 12

Bit	Byte Name	Description																														
7:0	PRTM12	<p>PortMap register for ports 1 &amp; 2</p> <p>When a hub is enumerated by a USB host controller, the hub is only permitted to report how many ports it has; the hub is not permitted to select a numerical range or assignment. The host controller will number the downstream ports of the hub starting with the number '1', up to the number of ports that the hub reported having.</p> <p>The host's port number is referred to as "logical port number" and the physical port on the hub is the "physical port number". When remapping mode is enabled (see PRTMAP_EN in Register 08h: Configuration Data Byte 3) the hub's downstream port numbers can be remapped to different logical port numbers (assigned by the host).</p> <p><b>Note:</b> The OEM must ensure that contiguous logical port numbers are used, starting from number '1' up to the maximum number of enabled ports; this ensures that the hub's ports are numbered in accordance with the way a host will communicate with the ports.</p>																														
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## 6.4.4.22 F3h: Port Map 3

Bit	Byte Name	Description																																	
7:0	PRTM3	<p>PortMap register for port 3.</p> <p>When a hub is enumerated by a USB host controller, the hub is only permitted to report how many ports it has; the hub is not permitted to select a numerical range or assignment. The host controller will number the downstream ports of the hub starting with the number '1', up to the number of ports that the hub reported having.</p> <p>The host's port number is referred to as "logical port number" and the physical port on the hub is the "physical port number". When remapping mode is enabled (see PRTMAP_EN in Register 08h: Configuration Data Byte 3) the hub's downstream port numbers can be remapped to different logical port numbers (assigned by the host).</p> <p><b>Note:</b> The OEM must ensure that contiguous logical port numbers are used, starting from number '1' up to the maximum number of enabled ports; this ensures that the hub's ports are numbered in accordance with the way a host will communicate with the ports.</p>																																	
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## 6.4.4.23 F4h-FAh: Reserved

Byte	Byte Name	Description
6:0	Reserved	Reserved.

## 6.4.4.24 FBh: Not Applicable

Bit	Byte Name	Description
7:0	Not Applicable	Not applicable.



## 6.4.4.25 FCh-FFh: Non-Volatile Storage Signature

Byte	Name	Description
3:0	NVSTORE_SIG	This signature is used to verify the validity of the data in the first 256 bytes of the configuration area. The signature must be set to 'ATA2' for USB2660/USB2660i.

## 6.4.5 INTERNAL FLASH MEDIA CONTROLLER EXTENDED CONFIGURATIONS

Enable Registers 100h - 17Fh by setting bit 7 of bmAttribute.

### 6.4.5.1 100h-106h: Combo LUN 0 Identifier String

Byte	Name	Description
6:0	CLUN0_ID_STR	If the device to LUN mapping bytes have configured this LUN to be a combo LUN, then these strings will be used to identify the LUN rather than the device identifier strings.

### 6.4.5.2 107h-10Dh: Combo LUN 1 Identifier String

BYTE	NAME	DESCRIPTION
6:0	CLUN1_ID_STR	If the device to LUN bytes have configured this LUN to be a combo LUN, then these strings will be used to identify the LUN rather than the device identifier strings.

### 6.4.5.3 10Eh-114h: Combo LUN 2 Identifier String

Byte	Name	Description
6:0	CLUN2_ID_STR	If the device to LUN mapping bytes have configured this LUN to be a combo LUN, then these strings will be used to identify the LUN rather than the device identifier strings.

### 6.4.5.4 115h-11Bh: Combo LUN 3 Identifier String

Byte	Name	Description
6:0	CLUN3_ID_STR	If the device to LUN mapping bytes have configured this LUN to be a combo LUN, then these strings will be used to identify the LUN rather than the device identifier strings.

### 6.4.5.5 11Ch-122h: Combo LUN 4 Identifier String

Byte	Name	Description
6:0	CLUN4_ID_STR	If the device to LUN mapping bytes have configured this LUN to be a combo LUN, then these strings will be used to identify the LUN rather than the device identifier strings.

### 6.4.5.6 123h-129h: Device 4 Identifier String

Byte	Name	Description
6:0	DEV4_ID_STR	This ID string is associated with the second Secure Digital / MultiMediaCard "SD/MMC2" device.

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## 6.4.5.7 130h-145h: Not Applicable

Byte	Name	Description
21:0	Not Applicable	Not applicable.

## 6.4.5.8 146h: Dynamic Number of Extended LUNs

Bit	Name	Description
7:0	DYN_NUM_EXT_LUN	<p>These bytes are used to specify the number of LUNs the device exposes to the host. These bytes are also used for icon sharing by assigning more than one LUN to a single icon. This is used in applications where the device utilizes a combo socket and the OEM wishes to have only a single icon displayed for one or more interfaces.</p> <p>If this field is set to "FF", the program assumes that you are using the default value and icons will be configured per the default configuration.</p>

## 6.4.5.9 147h-14Bh: Device to LUN Mapping

Byte	Name	Description
4:0	DEV_LUN_MAP	<p>These registers map a device controller (SD/MMC, SM (<a href="#">Note 6-2</a>), and MS) to a Logical Unit Number (LUN). The device reports the mapped LUNs to the USB host in the USB descriptor during enumeration. The icon installer associates custom icons with the LUNs specified in these fields.</p> <p>Setting a register to "FF" indicates that the device is not mapped. Setting all of the DEV_LUN_MAP registers for all devices to "FF" forces the use of the default mapping configuration. Not all configurations are valid. Valid configurations depend on the hardware, packaging, and OEM board layout. The number of unique LUNs mapped must match the value in the <a href="#">Section 6.4.3.7, "D3h: Dynamic Number of LUNs," on page 32</a>.</p>

## 6.4.5.10 14Ch-14Dh: Second Secure Digital Device Power Configuration

The device has two internal FETs which can be utilized for card power. For information about the other internal FET, please see [Section 6.4.2.3, "A4h-A5h: Smart Media Device Power Configuration," on page 30](#). The settings are stored in NVSTORE. This section describes the default internal configuration.

1. A card can be powered by an external FET or by an internal FET.
2. The power limit can be set to 100 mA or 200 mA (Default) for the internal FET.

Each media uses two bytes to store its device power configuration. Bit 3 selects between internal or external card power FET options. For internal FET card power control, bits 0 through 2 are used to set the power limit. The "Device Power Configuration" bits are ignored unless the "Enable Device Power Configuration" bit is set. See [Section 6.4.1.19, "9Ch-9Fh: Attribute Byte Descriptions," on page 29](#).

FET	Type	Bits	Bit Type	Description
0	FET Lo Byte SD2_PWR_LB	3:0	Low Nibble	0000b Disabled 0001b External FET enabled 1000b Internal FET with 100 mA power limit <b>1010b Internal FET with 200 mA power limit</b>
1		7:4	High Nibble	<b>0000b Disabled</b>
2	FET Hi Byte SD2_PWR_HB	3:0	Low Nibble	<b>0000b Disabled</b>
3		7:4	High Nibble	<b>0000b Disabled</b>

## 6.4.5.11 14Eh-17Bh: Not Applicable

Bit	Name	Description
47:0	Not Applicable	Not applicable.

## 6.4.5.12 17Ch -17Fh: Non-Volatile Storage Signature for Extended Configuration

Byte	Name	Description
3:0	NVSTORE_SIG2	This signature is used to verify the validity of the data in the upper 256 bytes if a 512 byte EEPROM is used, otherwise this bank is a read-only configuration area. The signature must be set to 'ecf1'.

## 6.4.6 I<sup>2</sup>C EEPROM

The I<sup>2</sup>C EEPROM interface implements a subset of the I<sup>2</sup>C Master Specification (Please refer to the Philips Semiconductor Standard I<sup>2</sup>C-Bus Specification for details on I<sup>2</sup>C bus protocols). The device's I<sup>2</sup>C EEPROM interface is designed to attach to a single "dedicated" I<sup>2</sup>C EEPROM, and it conforms to the Standard-mode I<sup>2</sup>C Specification (100 kbps transfer rate and 7-bit addressing) for protocol and electrical compatibility.

**Note:** Extensions to the I<sup>2</sup>C Specification are not supported. The device acts as the master and generates the serial clock SCL, controls the bus access (determines which device acts as the transmitter and which device acts as the receiver), and generates the START and STOP conditions.

### 6.4.6.1 Implementation Characteristics

The device will only access an EEPROM using the sequential read protocol.

### 6.4.6.2 Pull-Up Resistor

The circuit board designer is required to place external pull-up resistors (10 kΩ recommended) on the SPI\_DO / SDA / SPI\_SPD\_SEL and SPI\_CLK / SCL lines (per SMBus 1.0 Specification and EEPROM manufacturer guidelines) to VDD33 in order to assure proper operation.

## 6.4.7 IN-CIRCUIT EEPROM PROGRAMMING

The EEPROM can be programmed via automatic test equipment (ATE). Pulling nRESET low tri-states the device's EEPROM interface and allows an external source to program the EEPROM.

## 6.5 Default Configuration Option

The Microchip device can be configured via its internal default configuration. Please see [Section 6.3.2, "EEPROM Data Descriptor"](#) for specific details on how to enable default configuration. Please refer to [Table 6-1](#) for the internal default values that are loaded when this option is selected.

### 6.5.1 EXTERNAL HARDWARE NRESET

A valid hardware reset is defined as assertion of nRESET for a minimum of 1 μs after all power supplies are within operating range. While reset is asserted, the device (and its associated external circuitry) consumes less than 500 μA of current from the upstream USB power source.

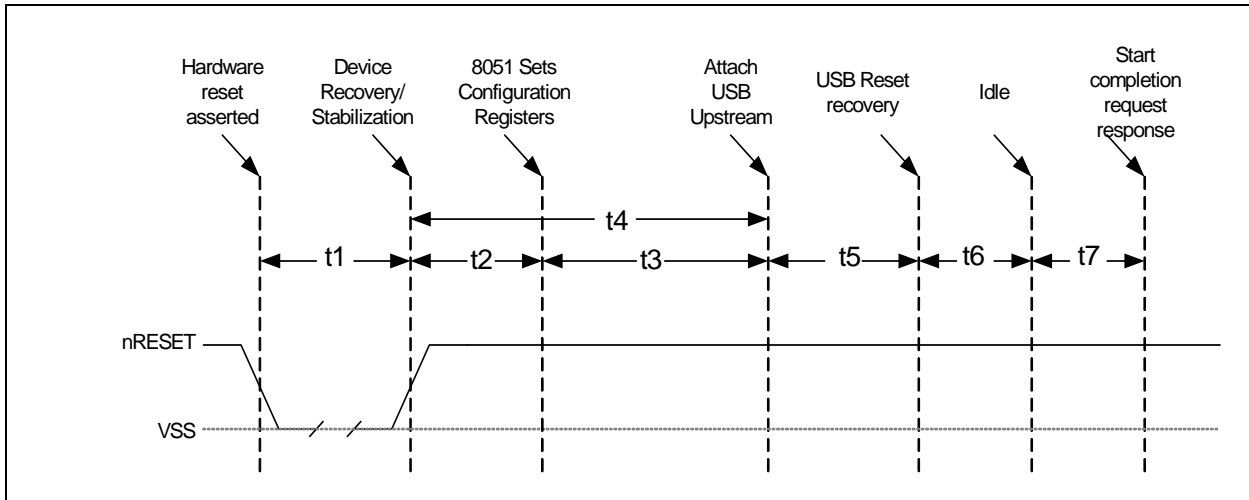
Assertion of nRESET (external pin) causes the following:

1. All downstream ports are disabled and PRTCTL power to downstream devices is removed.
2. The PHYs are disabled and the differential pairs will be in a high-impedance state.
3. All transactions immediately terminate; no states are saved.
4. All internal registers return to the default state (in most cases, 00h).
5. The external crystal oscillator is halted.
6. The PLL is halted.

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## 6.5.1.1 nRESET for EEPROM Configuration

**TABLE 6-7: NRESET TIMING FOR EEPROM MODE**



**TABLE 6-8: NRESET TIMING FOR EEPROM MODE**

Name	Description	MIN	TYP	MAX	Units
t1	nRESET asserted	1			μsec
t2	Device recovery/stabilization			500	μsec
t3	8051 programs device configuration		20	50	msec
t4	USB attach (See <b>Note</b> )			100	msec
t5	Host acknowledges attach and signals USB reset	100			msec
t6	USB idle		Undefined		msec
t7	Completion time for requests (with or without data stage)			5	msec

**Note:** All power supplies must have reached the operating levels mandated in [Section 8.0, "DC Parameters"](#), prior to (or coincident with) the assertion of nRESET.

## 6.5.2 USB BUS RESET

In response to the upstream port signaling a reset to the device, the device does the following:

**Note:** The device does not propagate the upstream USB reset to downstream devices.

1. Sets default address to '0'.
2. Sets configuration to: Unconfigured.
3. Negates PRTCTL[3:2] to all downstream ports.
4. Clears all TT buffers.
5. Moves device from suspended to active (if suspended).
6. Complies with Section 11.10 of the USB 2.0 Specification for behavior after completion of the reset sequence.

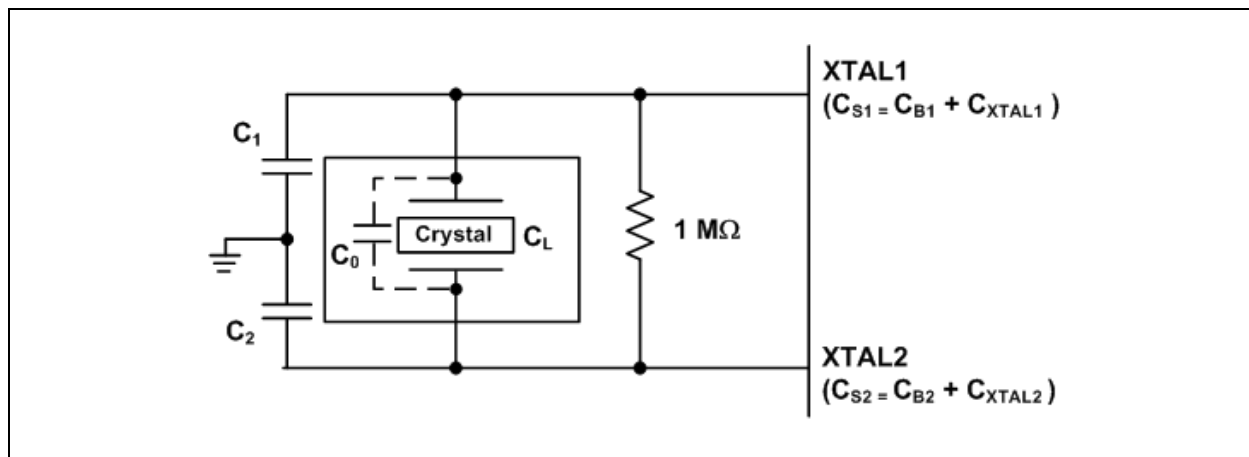
The host then configures the device and the device's downstream port devices in accordance with the USB 2.0 Specification.

## 7.0 AC SPECIFICATIONS

### 7.1 Oscillator/Crystal

Parallel Resonant, Fundamental Mode, 24 MHz ± 350 ppm.

**FIGURE 7-1: TYPICAL CRYSTAL CIRCUIT**



**TABLE 7-1: CRYSTAL CIRCUIT LEGEND**

Symbol	Description	In Accordance With
$C_0$	Crystal shunt capacitance	Crystal manufacturer's specification (See <a href="#">Note 7-1</a> )
$C_L$	Crystal load capacitance	
$C_B$	Total board or trace capacitance	OEM board design
$C_S$	Stray capacitance	MCHP IC and OEM board design
$C_{XTAL}$	XTAL pin input capacitance	MCHP IC
$C_1$ $C_2$	Load capacitors installed on OEM board	Calculated values based on <a href="#">Figure 7-2</a> (See <a href="#">Note 7-2</a> )

**FIGURE 7-2: CAPACITANCE FORMULAS**

$$C_1 = 2 \times (C_L - C_0) - C_{S1}$$

$$C_2 = 2 \times (C_L - C_0) - C_{S2}$$

**Note 7-1**  $C_0$  is usually included (subtracted by the crystal manufacturer) in the specification for  $C_L$  and should be set to '0' for use in the calculation of the capacitance formulas in [Figure 7-2](#). However, the OEM PCB itself may present a parasitic capacitance between XTAL1 and XTAL2. For an accurate calculation of  $C_1$  and  $C_2$ , take the parasitic capacitance between traces XTAL1 and XTAL2 into account.

**Note 7-2** Each of these capacitance values is typically approximately 18 pF.

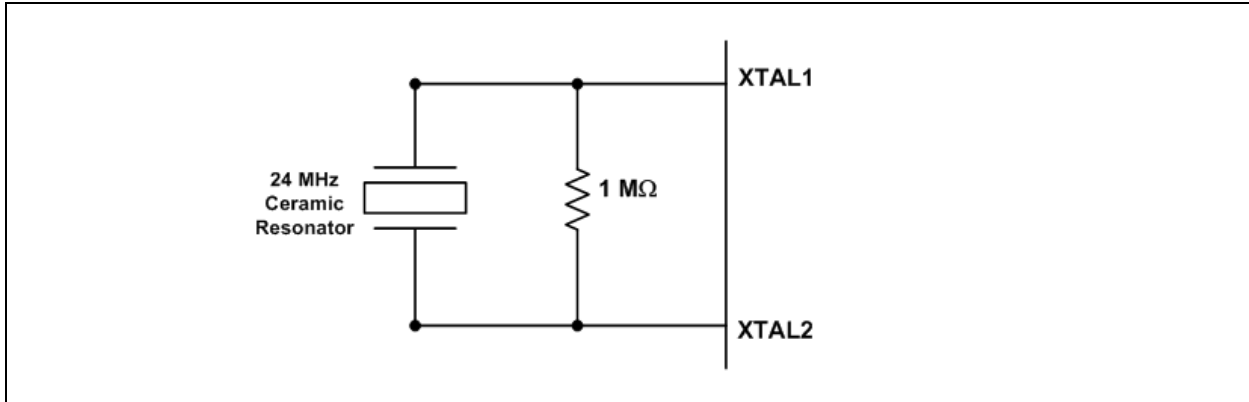
# USB2660/USB2660i

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## 7.2 Ceramic Resonator

24 MHz  $\pm$  350 ppm

**FIGURE 7-3: CERAMIC RESONATOR USAGE WITH MCHP IC**



## 7.3 External Clock

50% Duty cycle  $\pm$  10%, 24 MHz  $\pm$  350 ppm, Jitter < 100 ps rms.

The external clock is recommended to conform to the signaling level designated in the JESD76-2 specification on 1.8 V CMOS Logic. XTAL2 should be treated as a no connect.

### 7.3.1 I<sup>2</sup>C EEPROM

Frequency is fixed at 58.6 kHz  $\pm$  20%

### 7.3.2 USB 2.0

The Microchip device conforms to all voltage, power, and timing characteristics and specifications as set forth in the USB 2.0 Specification. Please refer to the USB 2.0 Specification for more information.

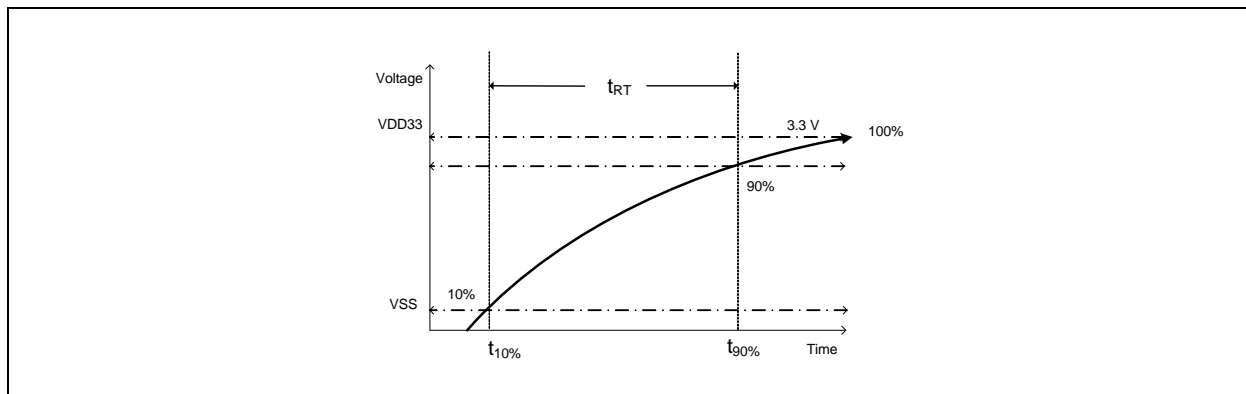
## 8.0 DC PARAMETERS

### 8.1 Maximum Ratings

Parameter	Symbol	MIN	MAX	Units	Comments
Storage Temperature	T <sub>STOR</sub>	-55	150	°C	
Lead Temperature				°C	Please refer to JEDEC specification J-STD-020D.
3.3 V supply voltage	VDD33	-0.5	4.0	V	
Voltage on USB+ and USB- pins		-0.5	(3.3 V supply voltage + 2) ≤ 6	V	
Voltage on CRD_PWR1 and CRD_PWR2		-0.5	VDD33 + 0.3	V	When internal power FET operation of these pins are enabled, these pins may be simultaneously shorted to ground or any voltage up to 3.63 V indefinitely, without damage to the device as long as VDD33 is less than 3.63 V and T <sub>A</sub> is less than 70°C.
Voltage on any signal pin		-0.5	VDD33 + 0.3	V	
Voltage on XTAL1		-0.5	3.6	V	
Voltage on XTAL2		-0.5	2.0	V	

**Note:** Stresses above the specified parameters may cause permanent damage to the device. This is a stress rating only. Functional operation of the device at any condition above those indicated in the operation sections of this specification is not implied. When powering this device from laboratory or system power supplies the absolute maximum ratings must not be exceeded or device failure can result. Some power supplies exhibit voltage spikes on their outputs when the AC power is switched on or off. In addition, voltage transients on the AC power line may appear on the DC output. When this possibility exists, a clamp circuit should be used.

**FIGURE 8-1: SUPPLY RISE TIME MODEL**



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## 8.2 Operating Conditions

Parameter	Symbol	MIN	MAX	Units	Comments
Commercial USB2660 Operating Temperature	$T_A$	0	70	°C	Ambient temperature in still air.
Industrial USB2660 Operating Temperature	$T_A$	-40	85	°C	Ambient temperature in still air.
3.3 V supply voltage	VDD33	3.0	3.6	V	A 3.3 V regulator with an output tolerance of 1% must be used if the output of the internal power FET's must support a 5% tolerance.
3.3 V supply rise time	$t_{RT}$	0	400	$\mu$ s	(Figure 8-1)
Voltage on USB+ and USB- pins		-0.3	5.5	V	If any 3.3 V supply voltage drops below 3.0 V, then the MAX becomes: $(3.3 \text{ V supply voltage}) + 0.5 \leq 5.5$
Voltage on any signal pin		-0.3	VDD33	V	
Voltage on XTAL1		-0.3	2.0	V	
Voltage on XTAL2		-0.3	2.0	V	

## 8.3 DC Electrical Characteristics

Parameter	Symbol	MIN	TYP	MAX	Units	Comments
<b>I, IPU, IPD Type Input Buffer</b>						
Low Input Level	$V_{ILI}$			0.8	V	TTL Levels
High Input Level	$V_{IHI}$	2.0			V	
Pull Down	PD		72		$\mu$ A	
Pull Up	PU		58		$\mu$ A	
<b>IS Type Input Buffer</b>						
Low Input Level	$V_{ILI}$			0.8	V	TTL Levels
High Input Level	$V_{IHI}$	2.0			V	
Hysteresis	$V_{HYSI}$		420		mV	
<b>ICLK Input Buffer</b>						
Low Input Level	$V_{ILCK}$			0.5	V	
High Input Level	$V_{IHCK}$	1.4			V	
Input Leakage	$I_{IL}$	-10		+10	$\mu$ A	$V_{IN} = 0$ to VDD33
<b>Input Leakage (All I and IS buffers)</b>						
Low Input Leakage	$I_{IL}$	-10		+10	$\mu$ A	$V_{IN} = 0$
High Input Leakage	$I_{IH}$	-10		+10	$\mu$ A	$V_{IN} = \text{VDD33}$



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Parameter	Symbol	MIN	TYP	MAX	Units	Comments
<b>I/O6, I/OD6PU Type Buffers</b>						
Low Output Level	$V_{OL}$			0.4	V	$I_{OL} = 6 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
High Output Level	$V_{OH}$	$V_{DD33} - 0.4$			V	$I_{OH} = -6 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
Output Leakage	$I_{OL}$	-10		+10	$\mu\text{A}$	$V_{IN} = 0 \text{ to } V_{DD33}$ (Note 8-1)
Pull Down	PD		72		$\mu\text{A}$	
Pull Up	PU		58		$\mu\text{A}$	
<b>O8, O8PD, O8PU, I/O8, I/O8PD, and I/O8PU Type Buffers</b>						
Low Output Level	$V_{OL}$			0.4	V	$I_{OL} = 8 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
High Output Level	$V_{OH}$	$V_{DD33} - 0.4$			V	$I_{OH} = -8 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
Output Leakage	$I_{OL}$	-10		+10	$\mu\text{A}$	$V_{IN} = 0 \text{ to } V_{DD33}$ (Note 8-1)
Pull Down	PD		72		$\mu\text{A}$	
Pull Up	PU		58		$\mu\text{A}$	
<b>O12, I/O12, and I/O12PD Type Buffers</b>						
Low Output Level	$V_{OL}$			0.4	V	$I_{OL} = 12 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
High Output Level	$V_{OH}$	$V_{DD33} - 0.4$			V	$I_{OH} = -12 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
Output Leakage	$I_{OL}$	-10		+10	$\mu\text{A}$	$V_{IN} = 0 \text{ to } V_{DD33}$ (Note 8-1)
Pull Down	PD		72		$\mu\text{A}$	
Pull Up	PU		58		$\mu\text{A}$	
<b>IO-U</b>						Note 8-2
<b>I-R</b>						Note 8-3

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Parameter	Symbol	MIN	TYP	MAX	Units	Comments
<b>I/O200 Integrated Power FET for CRD_PWR1 and CRD_PWR2</b>						
High Output Current	$I_{OUT}$	200			mA	$V_{drop_{FET}} = 0.46\text{ V}$
Low Output Current (Note 8-4)	$I_{OUT}$	100			mA	$V_{drop_{FET}} = 0.23\text{ V}$
On Resistance (Note 8-4)	$R_{DSON}$			2.1	$\Omega$	$I_{FET} = 70\text{ mA}$
Output Voltage Rise Time	$t_{DSON}$			800	$\mu\text{s}$	$C_{LOAD} = 10\text{ }\mu\text{F}$
<b>Integrated Power FET Set to 100 mA</b>						
Output Current (Note 8-4)	$I_{OUT}$	100			mA	$V_{drop_{FET}} = 0.22\text{ V}$
Short Circuit Current Limit	$I_{SC}$			140	mA	$V_{out_{FET}} = 0\text{ V}$
On Resistance (Note 8-4)	$R_{DSON}$			2.1	$\Omega$	$I_{FET} = 70\text{ mA}$
Output Voltage Rise Time	$t_{DSON}$			800	$\mu\text{s}$	$C_{LOAD} = 10\text{ }\mu\text{F}$
<b>Integrated Power FET Set to 200 mA</b>						
Output Current (Note 8-4)	$I_{OUT}$	200			mA	$V_{drop_{FET}} = 0.46\text{ V}$
Short Circuit Current Limit	$I_{SC}$			181	mA	$V_{out_{FET}} = 0\text{ V}$
On Resistance (Note 8-4)	$R_{DSON}$			2.1	$\Omega$	$I_{FET} = 70\text{ mA}$
Output Voltage Rise Time	$t_{DSON}$			800	$\mu\text{s}$	$C_{LOAD} = 10\text{ }\mu\text{F}$
<b>Supply Current Unconfigured</b>						
<b>Hi-Speed Host</b>						
USB2660	$I_{CCINTHS}$		70	80	mA	Note 8-5
USB2660i	$I_{CCINTHS}$		70	80	mA	
<b>Full Speed Host</b>						
USB2660	$I_{CCINITFS}$		65	75	mA	Note 8-5
USB2660i	$I_{CCINITFS}$		65	75	mA	
<b>Supply Current Configured</b>						
Hi-Speed Host, 1 downstream port						
USB2660	$I_{HCH1}$		260	270	mA	Note 8-5
USB2660i	$I_{HCH1}$		260	275	mA	
<b>Supply Current Configured</b>						
Hi-Speed Host, each additional downstream port						
USB2660			25	30	mA	Note 8-5
USB2660i			25	35	mA	
<b>Supply Current Configured</b>						
Full-Speed Host, 1 downstream port						
USB2660	$I_{FCC1}$		200	210	mA	Note 8-5
USB2660i	$I_{FCC1}$		200	215	mA	
<b>Supply Current Configured</b>						
Full-Speed Host, each additional downstream port						
USB2660			20	25	mA	Note 8-5
USB2660i			20	25	mA	

# USB2660/USB2660i

Parameter	Symbol	MIN	TYP	MAX	Units	Comments
<b>Supply Current Suspend</b>						(Note 8-5)
USB2660 USB2660i	$I_{CSBY}$ $I_{CSBY}$		500 500	950 1200	$\mu A$ $\mu A$	
<b>Supply Current Reset</b>						
USB2660 USB2660i	$I_{RST}$ $I_{RST}$		230 230	700 900	$\mu A$ $\mu A$	

**Note 8-1** Output leakage is measured with the current pins in high impedance.

**Note 8-2** See the USB 2.0 Specification, Chapter 7, for USB DC electrical characteristics

**Note 8-3** RBIAS is a 3.3 V tolerant analog pin.

**Note 8-4** Output current range is controlled by program software. The software disables the FET during short circuit condition.

**Note 8-5** Typical and maximum values were characterized using the following temperature ranges: The USB2660 supports the commercial temperature range of 0°C to +70°C  
The USB2660i supports the industrial temperature range of -40°C to +85°C

## 8.4 Capacitance

$T_A = 25^\circ C$ ;  $f_c = 1 \text{ MHz}$ ;  $V_{DD33} = 3.3 \text{ V}$

**TABLE 8-1: PIN CAPACITANCE**

Parameter	Symbol	Limits			Units	Test Condition
		MIN	TYP	MAX		
Clock Input Capacitance	$C_{XTAL}$			2	pF	All pins (except USB pins and pins under test) are tied to AC ground.
Input Capacitance	$C_{IN}$			10	pF	
Output Capacitance	$C_{OUT}$			20	pF	

# USB2660/USB2660i

## 9.0 PACKAGE SPECIFICATIONS

FIGURE 9-1: USB2660/USB2660I 64-PIN QFN

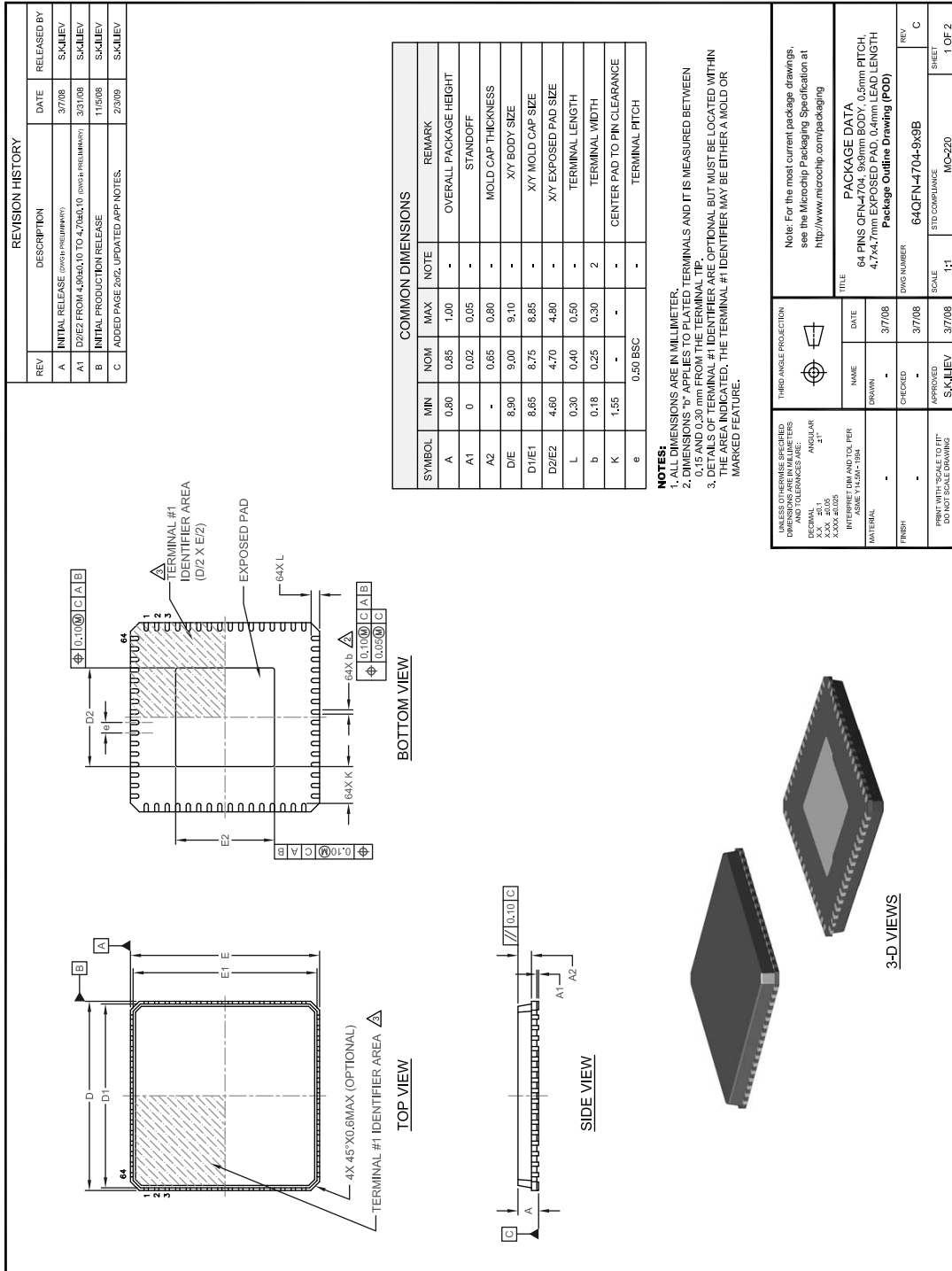
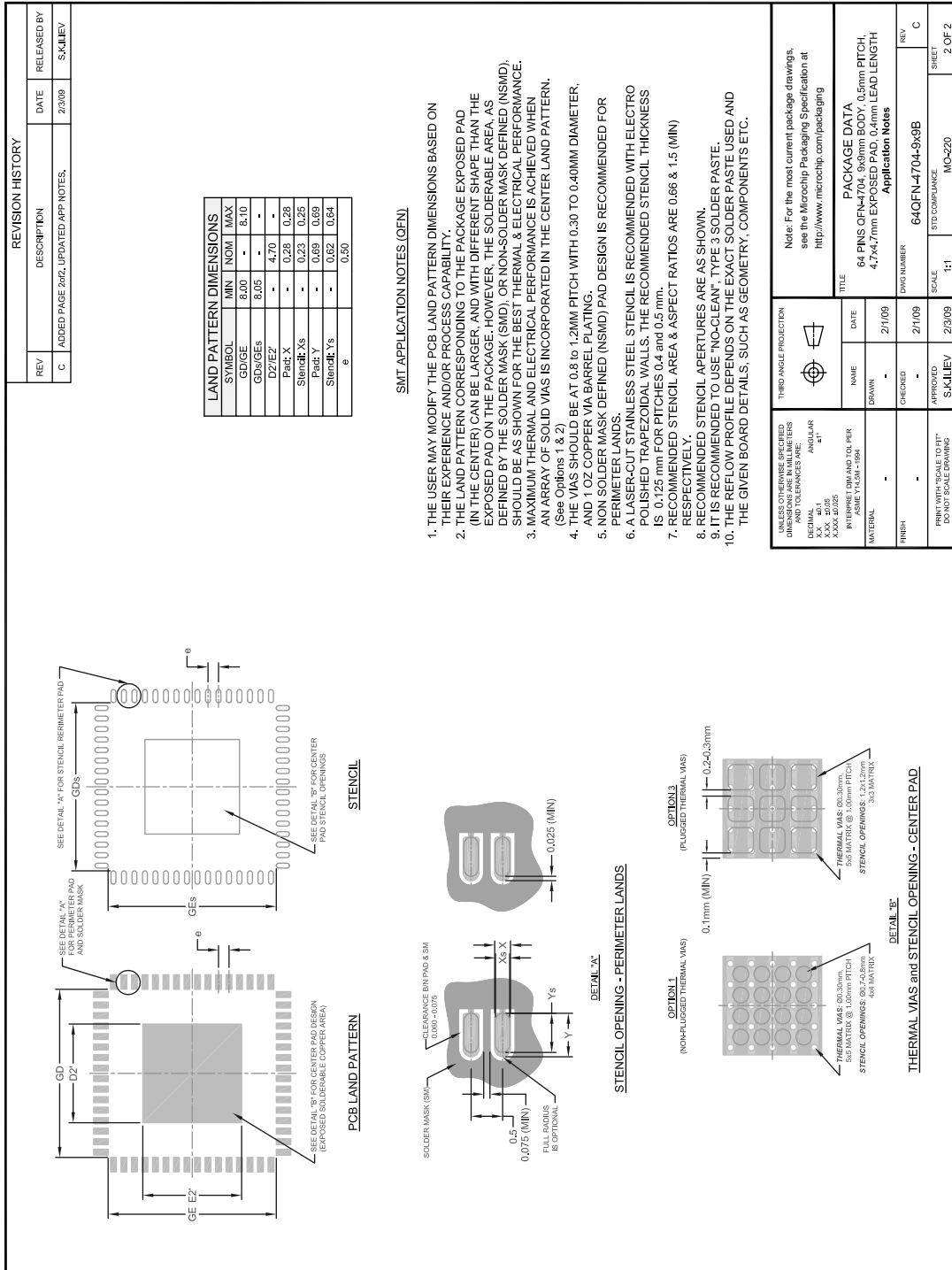
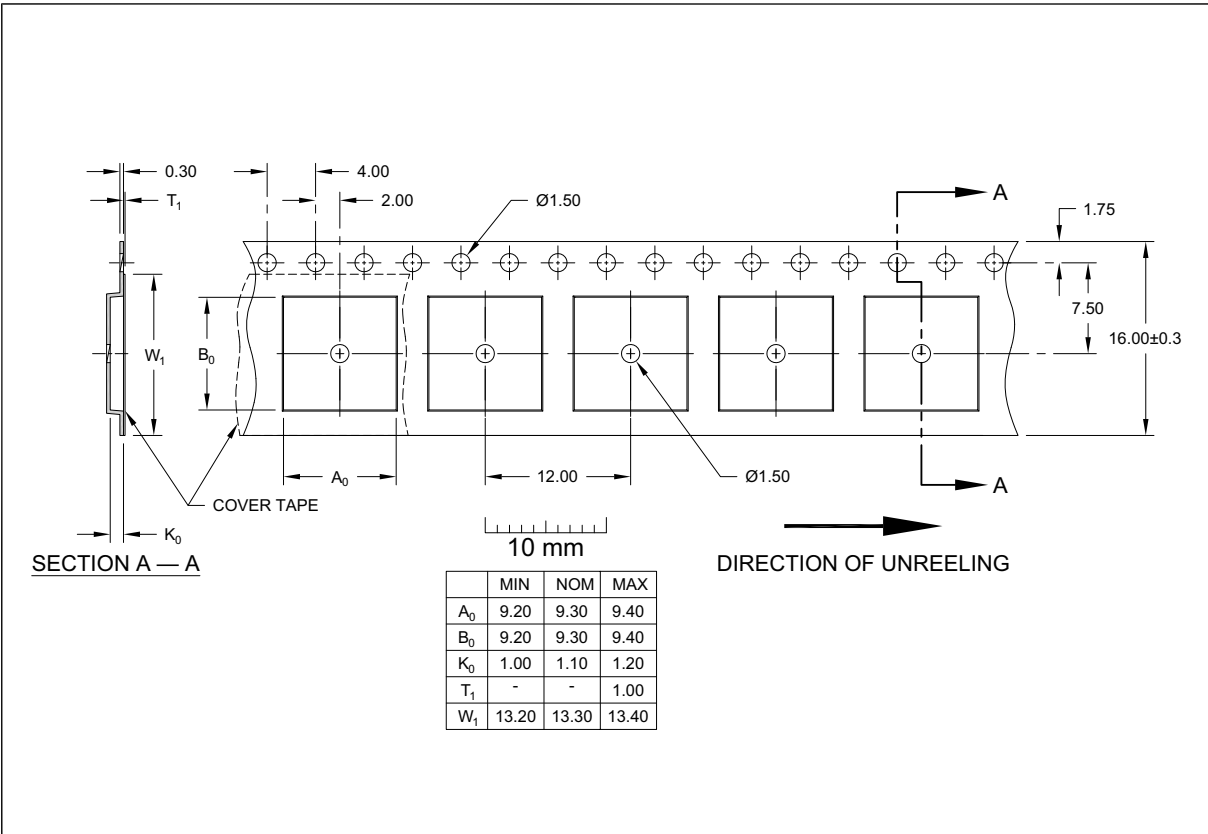


FIGURE 9-1: USB2660/USB2660I 64-PIN QFN (CONTINUED)



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FIGURE 9-2: 64-PIN PACKAGE TAPE SPECIFICATIONS



## APPENDIX A: ACRONYMS

<b>ACK:</b>	Handshake packet (positive acknowledgement)
<b>EOP:</b>	End of Packet
<b>EOF:</b>	End of (micro) Frame
<b>FM:</b>	Flash Media
<b>FMC:</b>	Flash Media Controller
<b>FS:</b>	Full-Speed Device
<b>LS:</b>	Low-Speed Device
<b>HS:</b>	Hi-Speed Device
<b>I<sup>2</sup>C<sup>®</sup>:</b>	Inter-Integrated Circuit <sup>1</sup>
<b>MMC:</b>	MultiMediaCard
<b>MS:</b>	Memory Stick
<b>MSC:</b>	Memory Stick Controller
<b>OCS:</b>	Over-current Sense
<b>PHY:</b>	Physical Layer
<b>PLL:</b>	Phase-Locked Loop
<b>RXD:</b>	Received eXchange Data
<b>SD:</b>	Secure Digital
<b>SDC:</b>	Secure Digital Controller
<b>TXD:</b>	Transmit eXchange Data
<b>UART:</b>	Universal Asynchronous Receiver-Transmitter
<b>UCHAR:</b>	Unsigned Character
<b>UINT:</b>	Unsigned Integer

1. I<sup>2</sup>C is a registered trademark of Philips Corporation.

# USB2660/USB2660i

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## APPENDIX B: DATA SHEET REVISION HISTORY

TABLE B-1: REVISION HISTORY

Revision	Section/Figure/Entry	Correction
DS00001931A (05-11-15)	Throughout document	GPIOs and SDIO support removed; Package Outline diagrams updated.
	REV A replaces previous SMSC version Rev. 1.1 (11-05-10)	



## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>[X]</u>	-	<u>XXX</u>	-	<u>[X]<sup>(1)</sup></u>																																				
Device	Temperature Range		Package		Tape and Reel Option																																				
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;"><b>Device:</b></td> <td colspan="5">USB2660, USB2660i</td> </tr> <tr> <td><b>Temperature Range:</b></td> <td>Blank</td> <td>=</td> <td>0°C to +70°C</td> <td>(Extended Commercial)</td> <td></td> </tr> <tr> <td></td> <td>i</td> <td>=</td> <td>-40°C to +85°C</td> <td>(Industrial)</td> <td></td> </tr> <tr> <td><b>Package:</b></td> <td>JZX</td> <td>=</td> <td colspan="3">64-pin QFN</td> </tr> <tr> <td><b>Tape and Reel Option:</b></td> <td>Blank</td> <td>=</td> <td colspan="3">Standard packaging (tray)</td> </tr> <tr> <td></td> <td>TR</td> <td>=</td> <td colspan="3">Tape and Reel<sup>(1)</sup></td> </tr> </table>						<b>Device:</b>	USB2660, USB2660i					<b>Temperature Range:</b>	Blank	=	0°C to +70°C	(Extended Commercial)			i	=	-40°C to +85°C	(Industrial)		<b>Package:</b>	JZX	=	64-pin QFN			<b>Tape and Reel Option:</b>	Blank	=	Standard packaging (tray)				TR	=	Tape and Reel <sup>(1)</sup>		
<b>Device:</b>	USB2660, USB2660i																																								
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<b>Tape and Reel Option:</b>	Blank	=	Standard packaging (tray)																																						
	TR	=	Tape and Reel <sup>(1)</sup>																																						
<p><b>Examples:</b></p> <ul style="list-style-type: none"> <li>a) USB2660-JZX 64-pin QFN, 9 x 9mm RoHS Compliant Package, Tray</li> <li>b) USB2660i-JZX-03 64-pin QFN, 9 x 9mm RoHS Compliant Package, Tray</li> <li>c) USB2660i-JZX-03-TR 64-pin QFN, 9 x 9mm RoHS Compliant Package, Tape &amp; Reel</li> </ul> <p><b>Note 1:</b> Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape &amp; Reel option. Reel size is 3,000.</p>																																									

# USB2660/USB2660i

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